

HSF Property:ROHS

ACER  
JM31/SJM31/BAP31  
Discrete  
MAIN BOARD

2009.05.26

Tuesday, May 26, 2009		A03
DATE	CHANGE NO.	REV

	EE	DATE	POWER	DATE	INVENTEC			
DRAWER					TITLE			
DESIGN					BAP31G SFF			
CHECK					SIZE			
RESPONSIBLE					CODE			
SIZE					DOC NUMBER			
FILE NAME: XXXX.XXXXXX.XX					D-CS-1310A2264501-ALG			
PIN	XXXXXX000000				SHEET	1	of	47

# 1. Schematic Page Description :

## Montevina Schematic Ver : A03

1. Title

2. Schematic Page DESCR

3. Block Diagram

4. Annotations

5. Schematic Modify

6. Timing Diagram

7. Power Block Diagram

8. Adaptor in/Charge

9. 5VLA/5VA/3VA

10. 3VS/5VS/1.5V (DDR3)

11. 1.05VS/1.5S/1.8V/1.5VA

12. Power Latch/1.5VS/SCREW HOLE

13. CPU Core Power

14. GPU Core Power

15. Penryn Processor(1/2)

16. Penryn Processor(2/2)

17. CPU Thermal

18. Cantiga Host(1/6)

19. Cantiga DMI/Graph(2/6)

20. Cantiga DDRII(3/6)

21. Cantiga Power(4/6)

22. Cantiga Power(5/6)

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27. ICH9M CPU/IDE/SATA(1/4)

28. ICH9M PCI/PCIE/DMI/USB(2/4)

29. ICH9M GPIO(3/4)

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31. LCD CNN/SATA/3G/WLAN

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34. IO CN

35. IO CN

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38. M92-S2(1/5)

39. M92-S2(2/5)

40. M92-S2(3/5)

41. M92-S2(4/5)

42. M92-S2(5/5)

43. DDR3 VRAM

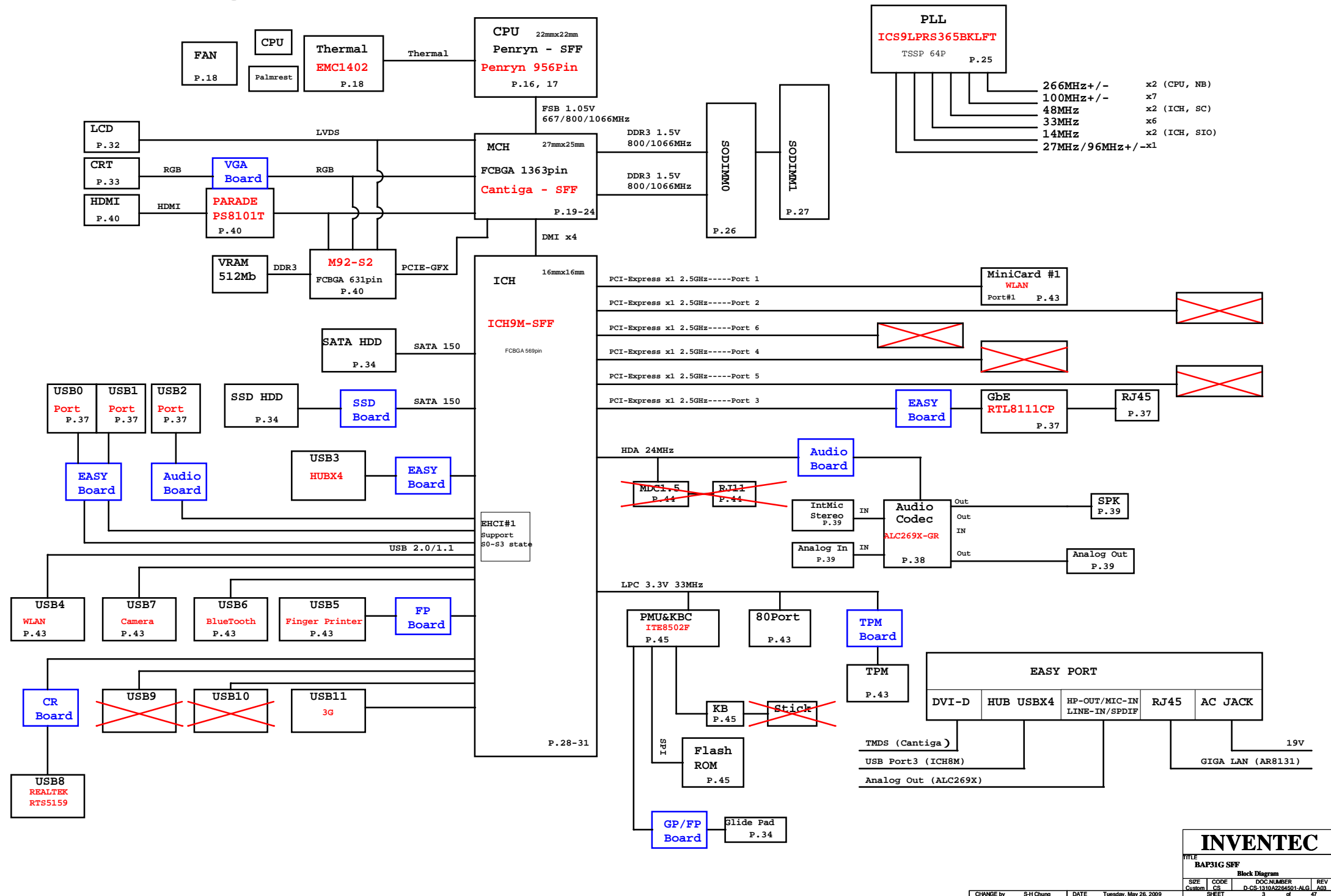
44. HyBrid Switch

45. dGPU Power

46. dGPU Power

47. dGPU Power

# 3. Block Diagram :



# 4. Net name Description :

## Voltage Rails

DCIN	Primary DC system power supply
+5VLA	5.0V always on power rail by LATCH or ACIN
+5VA	5.0V always on power rail by ECPWON
+3VA	3.3V always on power rail by ECPWON
+5VS	5.0V switched power rail by SLP_S3#_3R
+3VS	3.3V switched power rail by SLP_S3#_3R
+1.8VS	1.8V switched power rail by SLP_S3#_3R
VCC_CORE	Core Voltage for CPU
+1.05VS	1.05V power rail for AGTL+ termination/Core for GMCH by SLP_S3#_3R
+1.25VS	1.25V switched power rail by SLP_S3#_3R
+1.5VS	1.5V power rail for CPU PLL/DMI/PCIE;DDRIII DLLs for GMCH/Core;PCIE for ICH9m by SLP_S3#_3R
+1.5V	1.5V power rail for DDRII by SLP_S5#_3R
0.75VDDT_DDRIII	0.75V DDRII Termination Voltage by SLP_S3#_3R

## Part Naming Conventions

C	=	Capacitor
CN	=	Connector
D	=	Diode
F	=	Fuse
L	=	Inductor
Q	=	Transistor
R	=	Resistor
RP	=	Resistor Pack
U	=	Arbitrary Logic Device
Y	=	Crystal and Osc

## Net Name Suffix

#	=	Active Low signal
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# 5. Board Stack up Description

## PCB Layers

Layer 1		Component Side, Microstrip signal Layer
Layer 2		Ground Plane
Layer 3		Stripline Layer
Layer 4		Power Plane
Layer 5		Stripline Layer
Layer 6		Stripline Layer
Layer 7		Ground Plane
Layer 8		Solder Side, Microstrip signal Layer

	Differential Impedance for Microstrip	Differential Impedance for Stripline
Host Clock	95 ohm +/- 20%	95 ohm +/- 20%
PCI-E Clock	95 ohm +/- 20%	95 ohm +/- 20%
DDR3 CLK	75 ohm +/- 20%	75 ohm +/- 20%
DDR3 Strobe	90 ohm +/- 20%	90 ohm +/- 20%
DMI Bus	95 ohm +/- 20%	95 ohm +/- 20%
PCIE Bus	95 ohm +/- 20%	95 ohm +/- 20%
SDVO	95 ohm +/- 20%	95 ohm +/- 20%
SATA	95 ohm +/- 20%	95 ohm +/- 20%
USB	90 ohm +/- 20%	90 ohm +/- 20%
LVDS	95 ohm +/- 20%	95 ohm +/- 20%
Lan	95 ohm +/- 20%	95 ohm +/- 20%

Power Rail	Destination	Voltage	S0 Current
VCC_CORE	Penryn SFF HFM, LFM:	1.3319V~1.4375V~1.4591V 0.9221V~0.9625V~0.9739V	18A
1.05VS	Penryn SFF : AGTL+ termination Cantiga GS: Core Cantiga GS: PCIE Cantiga GS:Core+IMEL+HSIO Cantiga GS:VCC_GMCH Cantiga GS:VCCA_SM_CK and NCTF Cantiga GS:VCC_DMI Cantiga GS:VCCA_SM Cantiga GS:VTT ICH9M:VCC1_05 ICH9M:DMI ICH9M:CPU_IO	1V~1.05V~1.10V 0.997V~1.05V~1.102V 0.9975V~1.05V~1.1025V 0.9975V~1.05V~1.1025V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V	4.5A 8.7A 1.78A 2.898A 10.154A 37.95mA 456mA 747.5mA 852mA 1.634A 48mA 2mA
1.5VS	Penryn SFF PLL Cantiga GS: QDAC Cantiga GS: LVDS Cantiga GS: TVDAC Cantiga GS: Various PLLS analog supply Cantiga GS: VCC_SM_CK Cantiga GS: VCC_SM ICH9M:PCIE_ICH ICH9M:SATA_ICH ICH9M:VCC_GLAN Mini Card: Express Card:	1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.71V~1.8V~1.89V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V	130mA 0.5mA 60.31mA 35mA 485mA 149.5mA 3.1625A 646mA 1.342A 80mA
1.5V	Cantiga GS: DDRIII System Memory	1.425V~1.5V~1.575V	650mA
0.75VDDT_DDRIII	Terminator:	0.7125V~0.75V~0.7875V	3.1A(800M) 4.1A(1067M)
3VS	Cantiga GS: HV CMOS Cantiga GS: VCCS_TVDAC ICH9M:VCC3_3 ICH9M:VCCGLAN3_3 Thermal Sensor: Mini Card: UMTS Express Card: CLK Generator: ICS9LPRS365BKLF Mini Card: WirelessLan Bluetooth: Super I/O: IT8305E Azalia Codec: ALC262 Azalia MDC:	3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.0V~3.3V~3.6V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.0V~3.3V~3.6V 3.0V~3.3V~3.6V	105.3mA 78mA 308mA 1mA 5mA 1.3A 500mA
1.8VS	DVI	3.0V~3.3V~3.6V	120mA
3VA	ICH9M: RTC ICH9M:VCCSUS3_3 ICH9M:VCCCL3_3 ICH9M:VCCLAN3_3 LCD: Lan:AR8131 Azalia MDC: Flash ROM: BIOS	2V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.0V~3.3V~3.6V 3.0V~3.3V~3.6V 3.0V~3.3V~3.6V	6uA 212mA 73mA 78mA 2A 1A
5VS	Cardreader: RTS5159 Azalia Codec: ALC269 HDD: SATA ODD: SATA Audio AMP: G1432 Inverter: WebCam	3.0V~3.3V~3.6V 3.0V~3.3V~3.6V 4.75V~5.0V~5.25V 4.75V~5.0V~5.25V 4.75V~5.0V~5.25V	Max: 1.5A ; R/W: 460mA ; STDBY: 70mA Max: 1.5A ; R/W: 900mA ; STDBY: 45mA
5VA	USB: x 2 ports USB	4.75V~5.0V~5.25V 5VA	1A 2A 1.5A
5VLA	Control Power		
3VLA	EC: ITE8512E	3.0V~3.3V~3.6V	300mA

INVENTEC

BAP31G SFF

ANNOTATIONS

SIZE

CODE

DOCNUMBER

REV

Custom

CS

D-CS-1310A2284501-ALG\_A03

SHEET

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of

47

# 6.Schematic modify Item and History :

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- 2009.0108
1. ADD USB P3 for Docking, USB P5 for Finger printer,  
Modify CN5 -----P28

2. Modify CN20 to 50pin-----P33

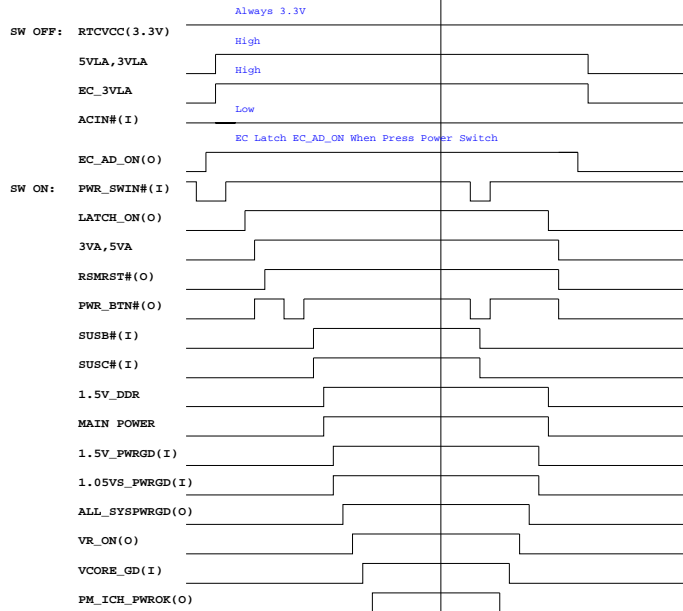
3. Move PWR\_SWIN# from CN14 to CN20

4. ADD TPM module-----P34
- 2009.0109
1. ADD DOCK\_USB\_EN, DOCK\_CRT\_IN#-----P32,33
- 2009.0112
1. Change power item: R490,R291,BAT CNN TH PIN

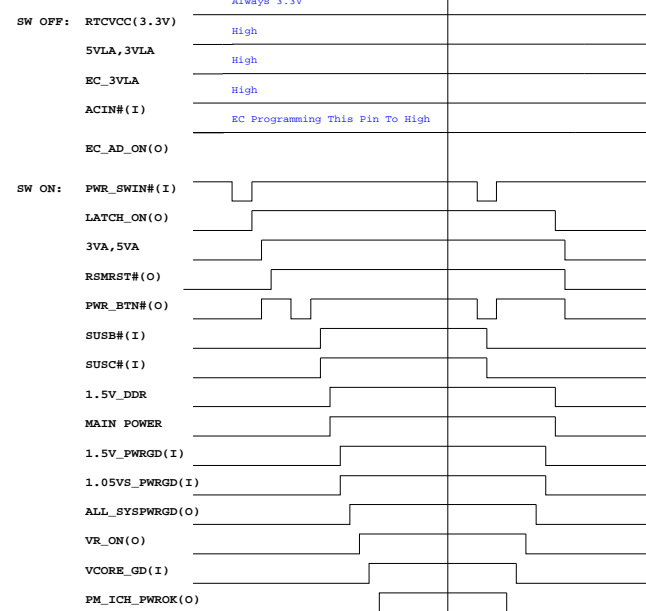
## SYSTEM POWER ON/OFF SEQUENCE

## Power on/off sequence AC insert (without Battery Pack)

Power on sequence Power off sequence

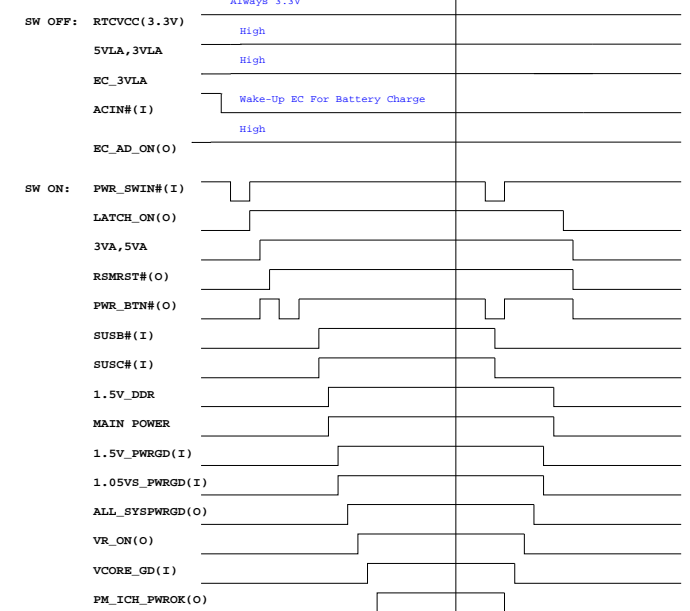
Power on/off sequence Battery insert  
(without AC adapter)

Power on sequence Power off sequence



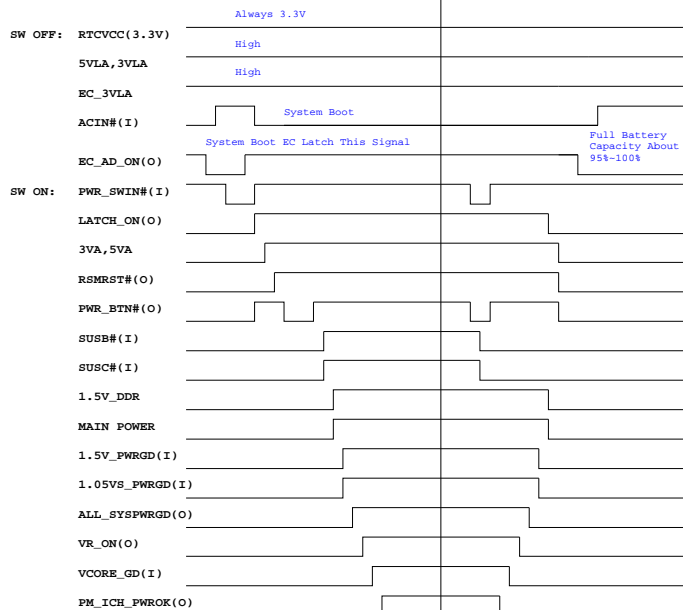
## Power on/off sequence AC insert(with charge over 95%)

Power on sequence Power off sequence



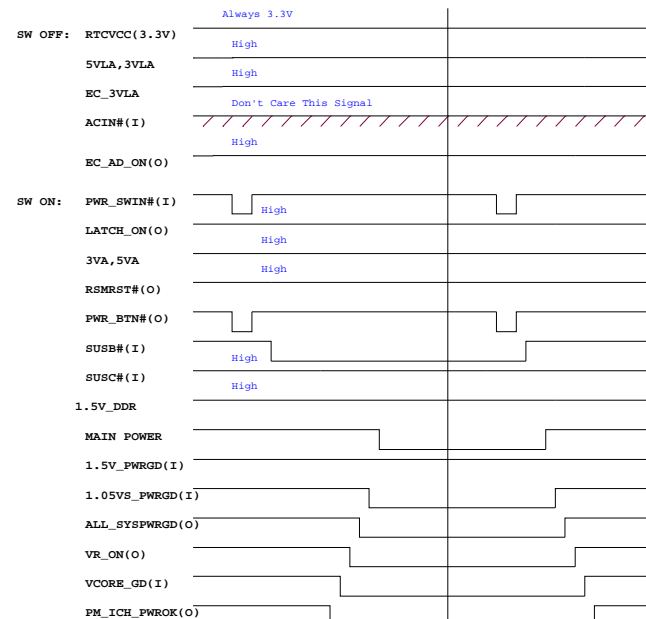
## Power on/off sequence AC insert(without charge over 95%)

Power on sequence Power off sequence



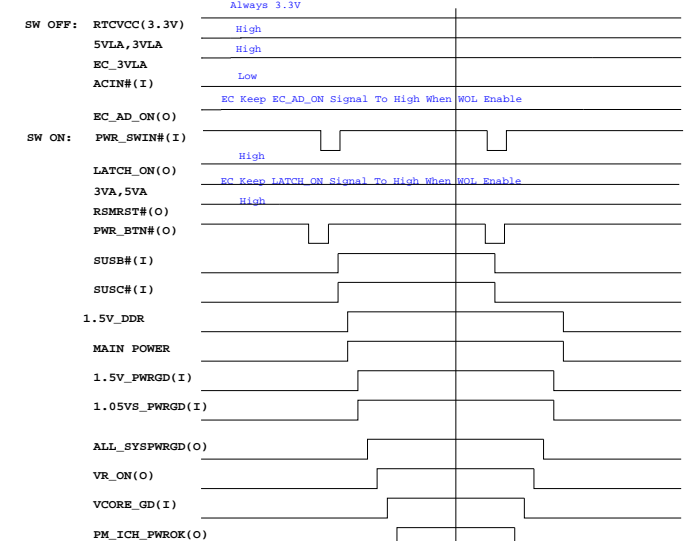
## Suspend And Resume Sequence (S3)

Suspend sequence Resume sequence



## Power on/off sequence after windows shutdown (WOL enable)

Suspend sequence Resume sequence



INVENTEC

TITLE  
BAP31G SFF

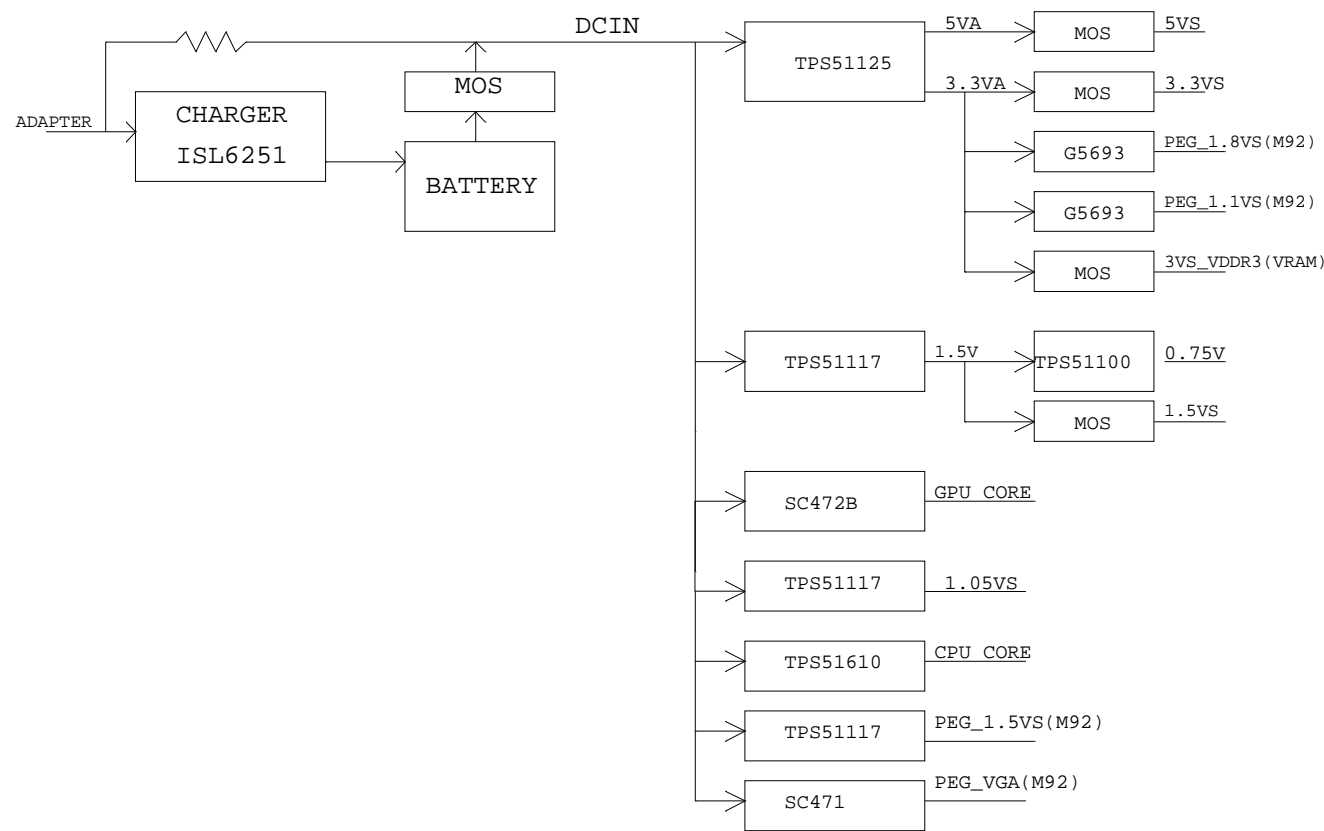
Time Diagram

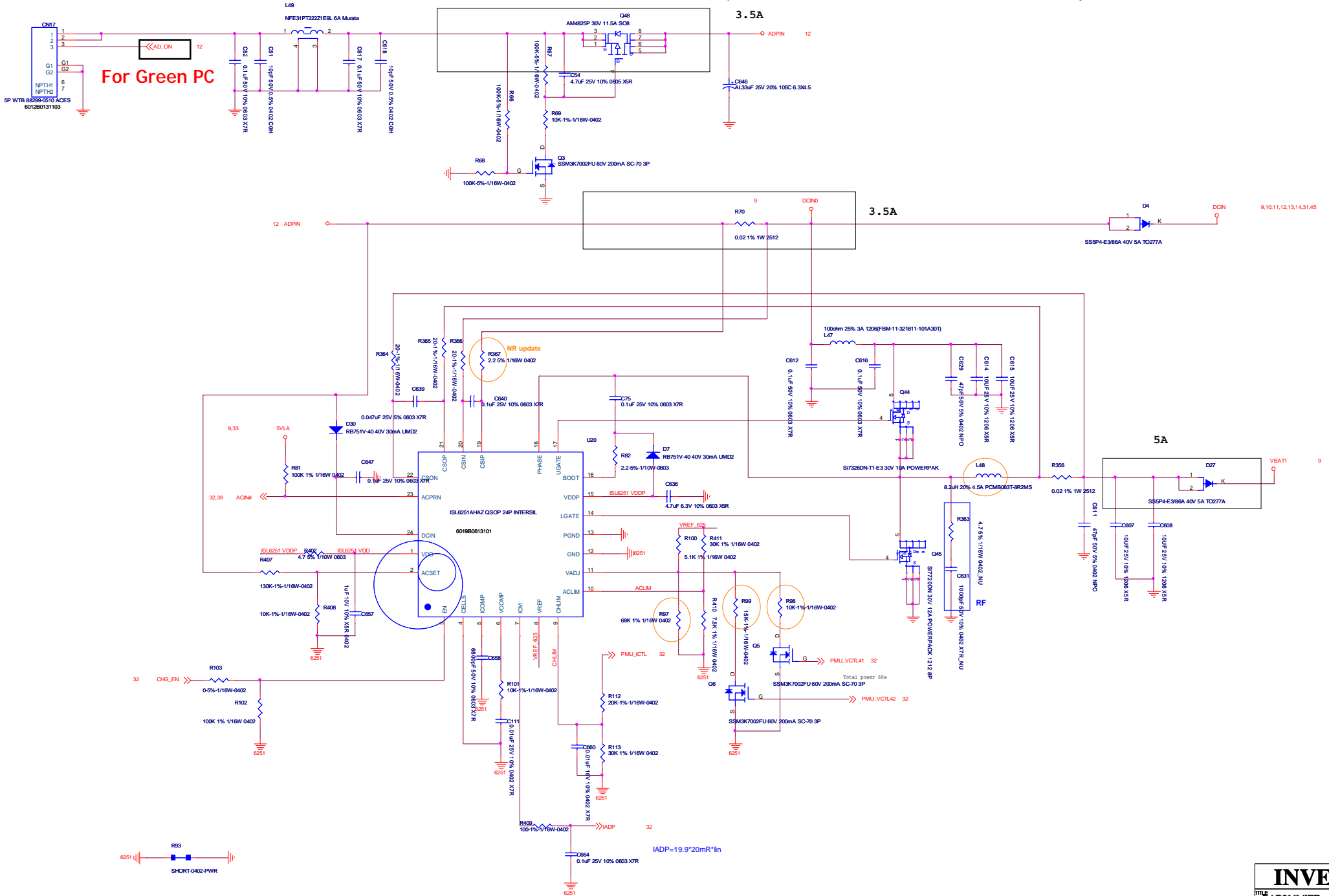
SIDE CODE DOC NUMBER REV

Custom CS DCS-1310A2264501-ALG 47

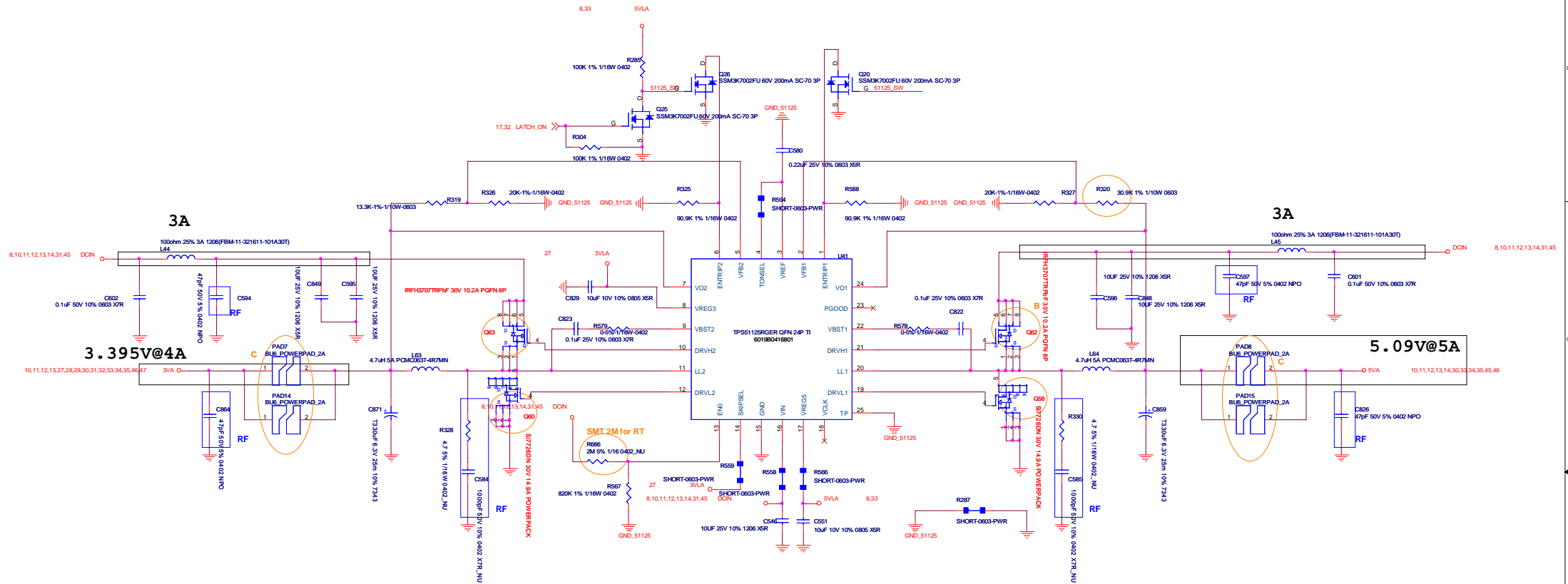
CHANGE by S-H Chung DATE Tuesday, May 28, 2009 SHEET 6 of 47

# Power Block Diagram :

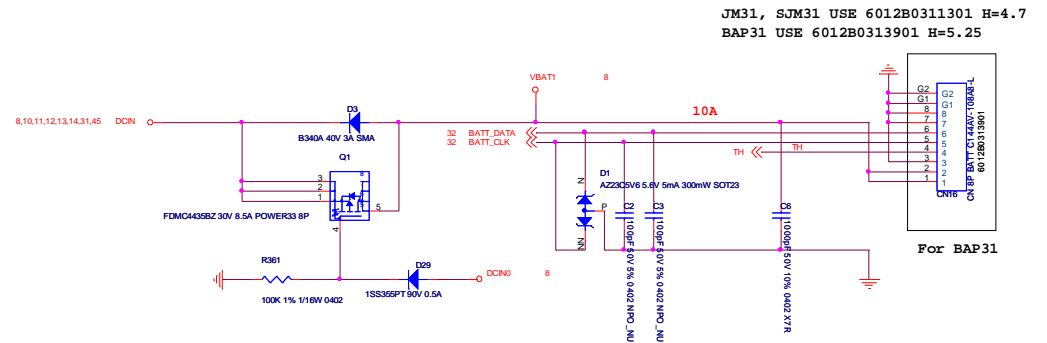
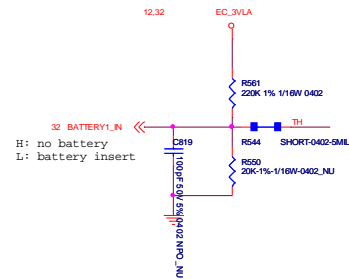
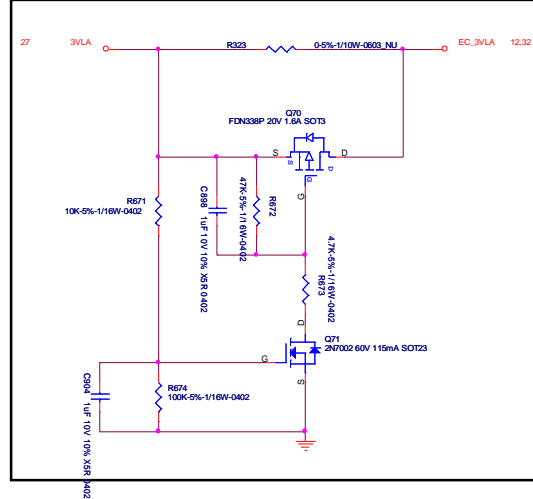








For Green PC

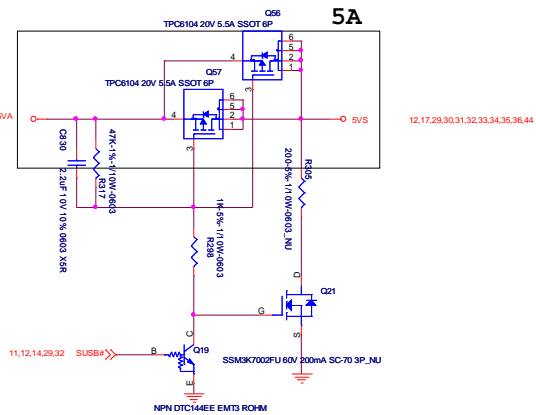
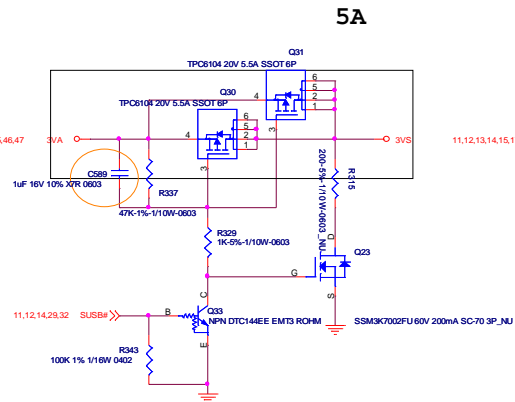
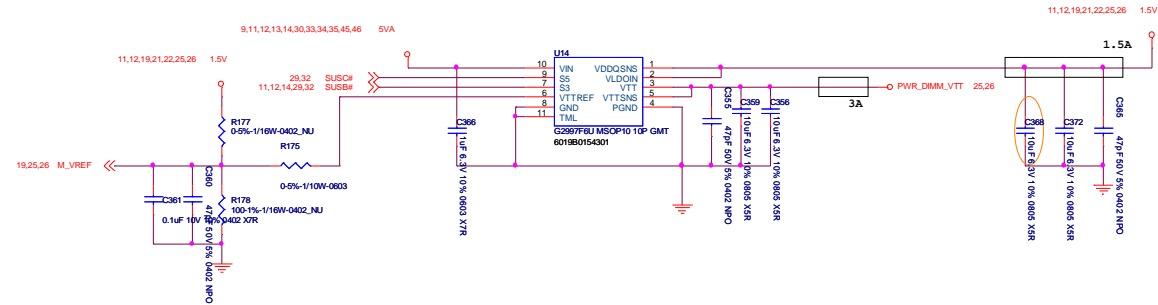
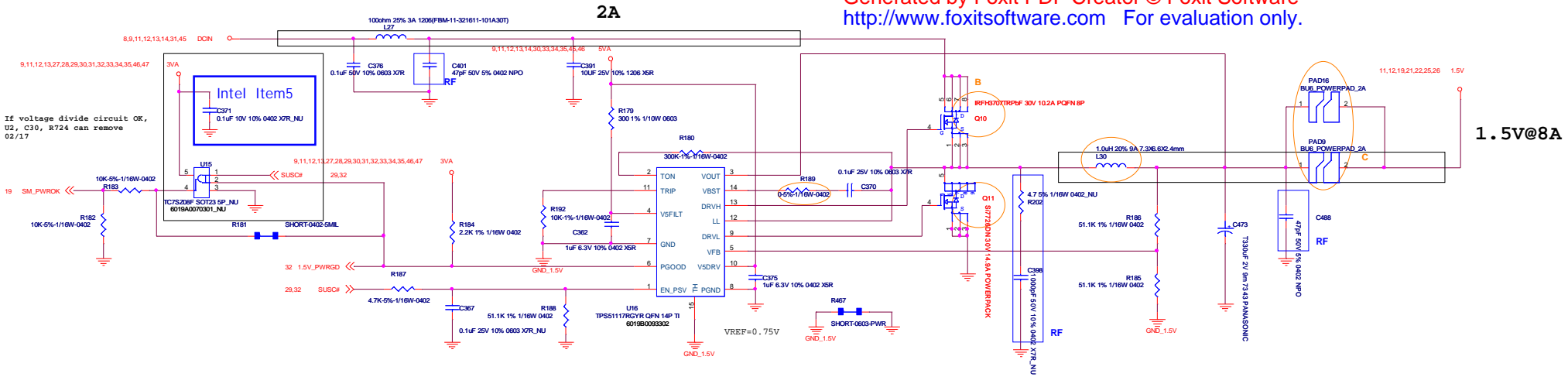


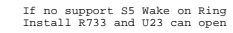
For BAP31

**INVENTEC**

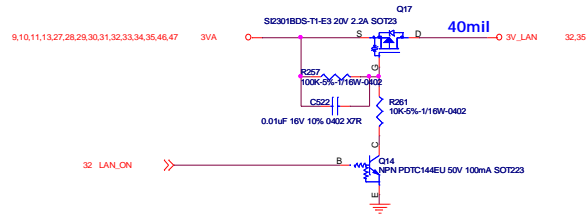
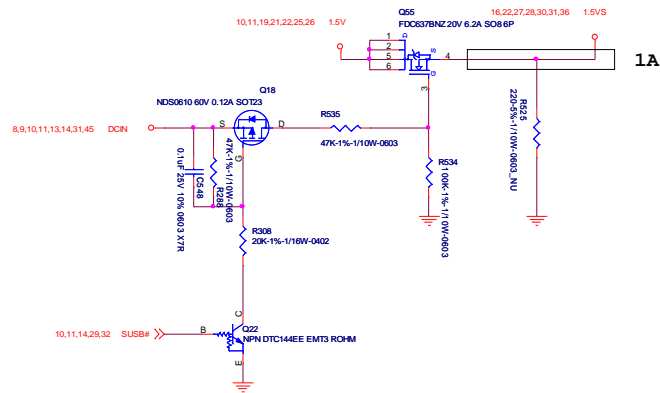
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5VLA/5VA/3VLA/3VA			
SIZE Custom	CODE CS	DOC. NUMBER D-CS-1310A2284501-ALG	
SHEET		9	of 47

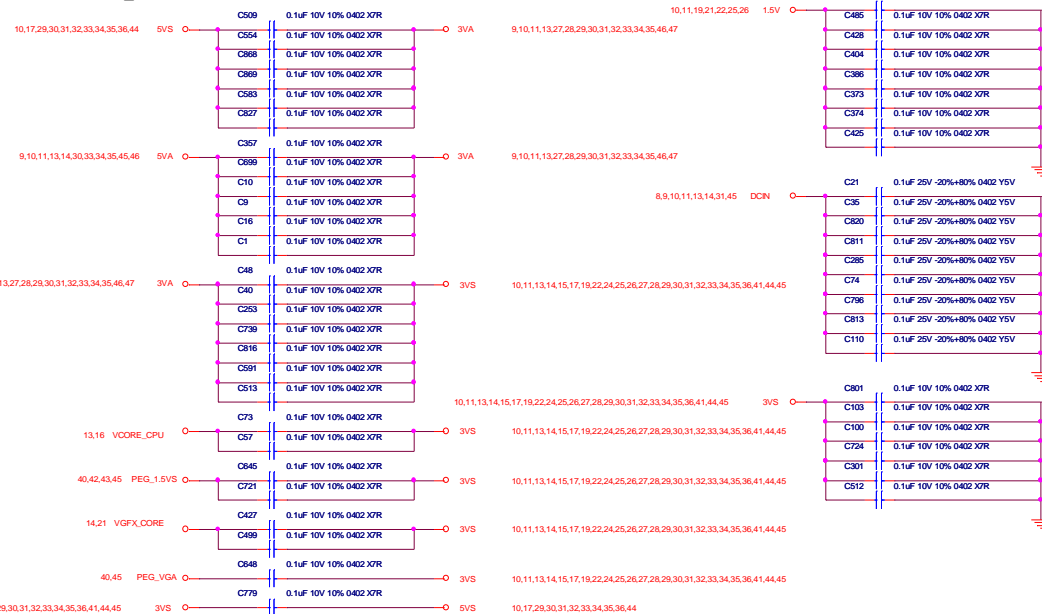




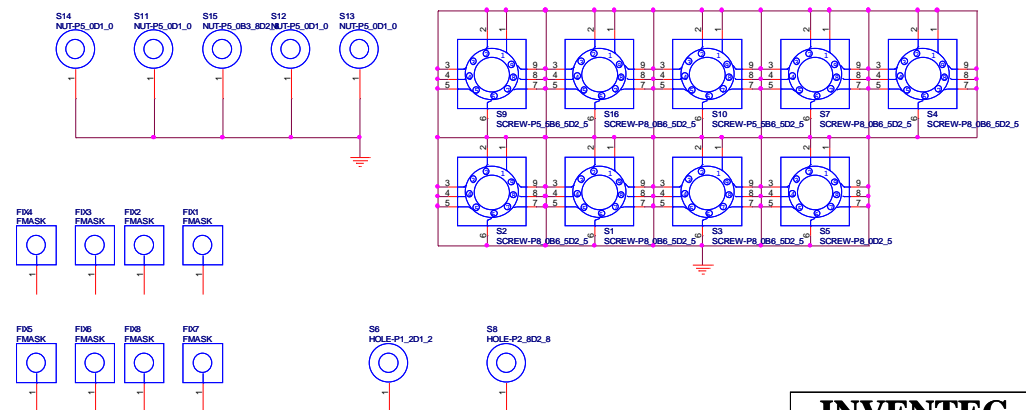
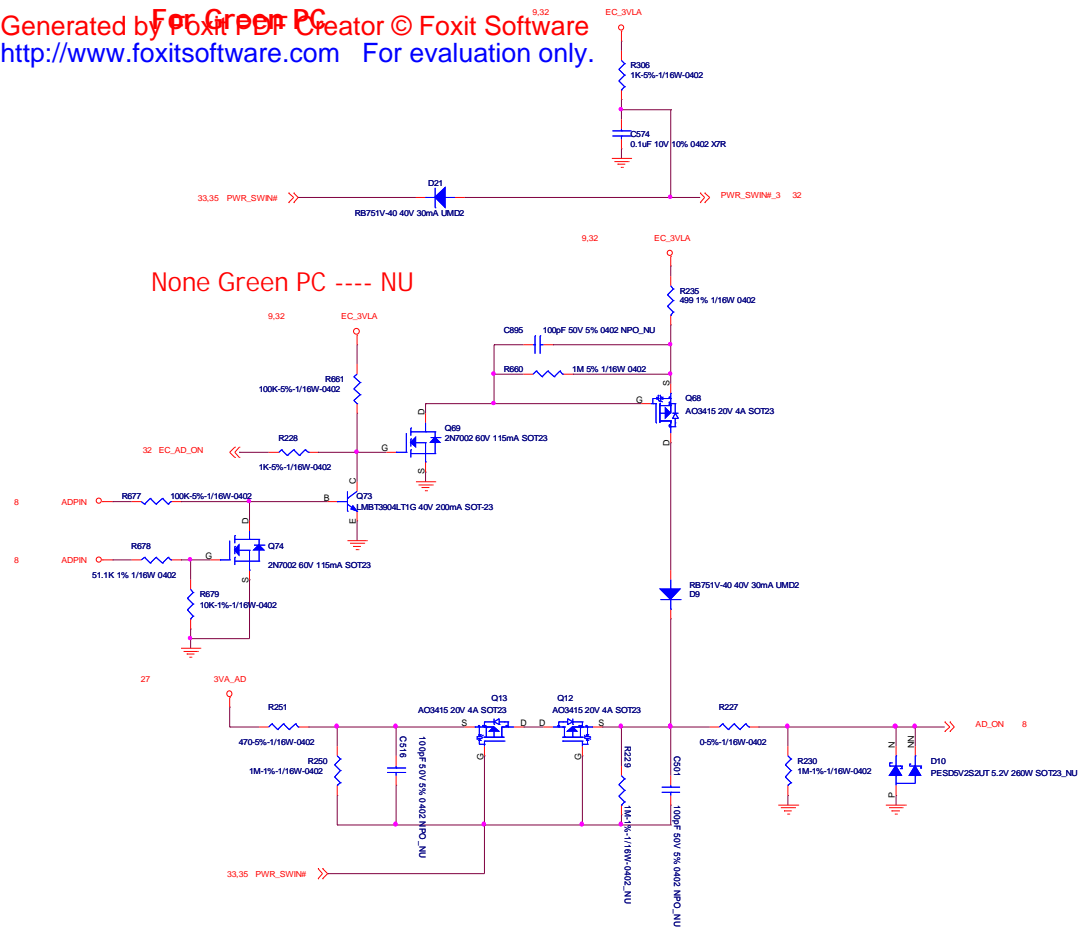
1.5VS



## EMI Cap

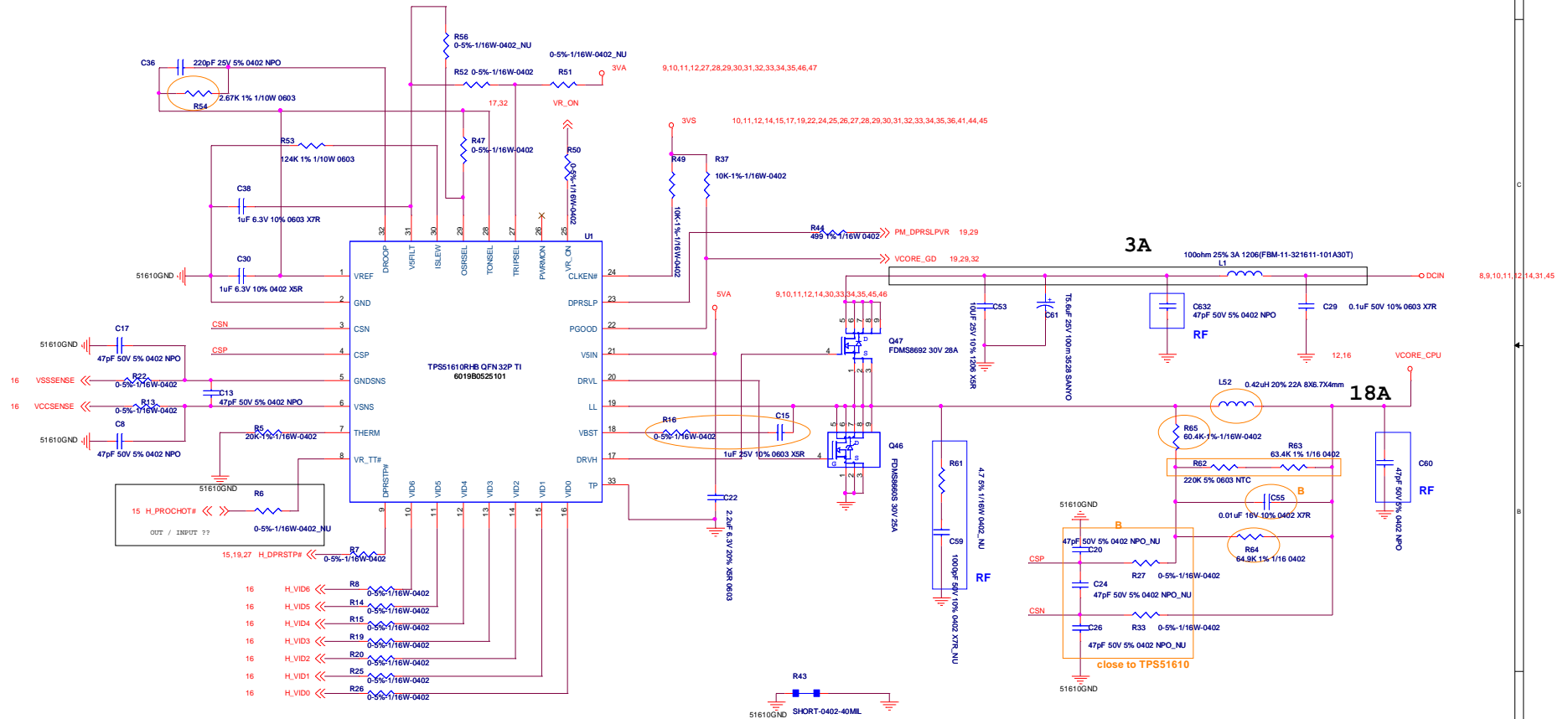


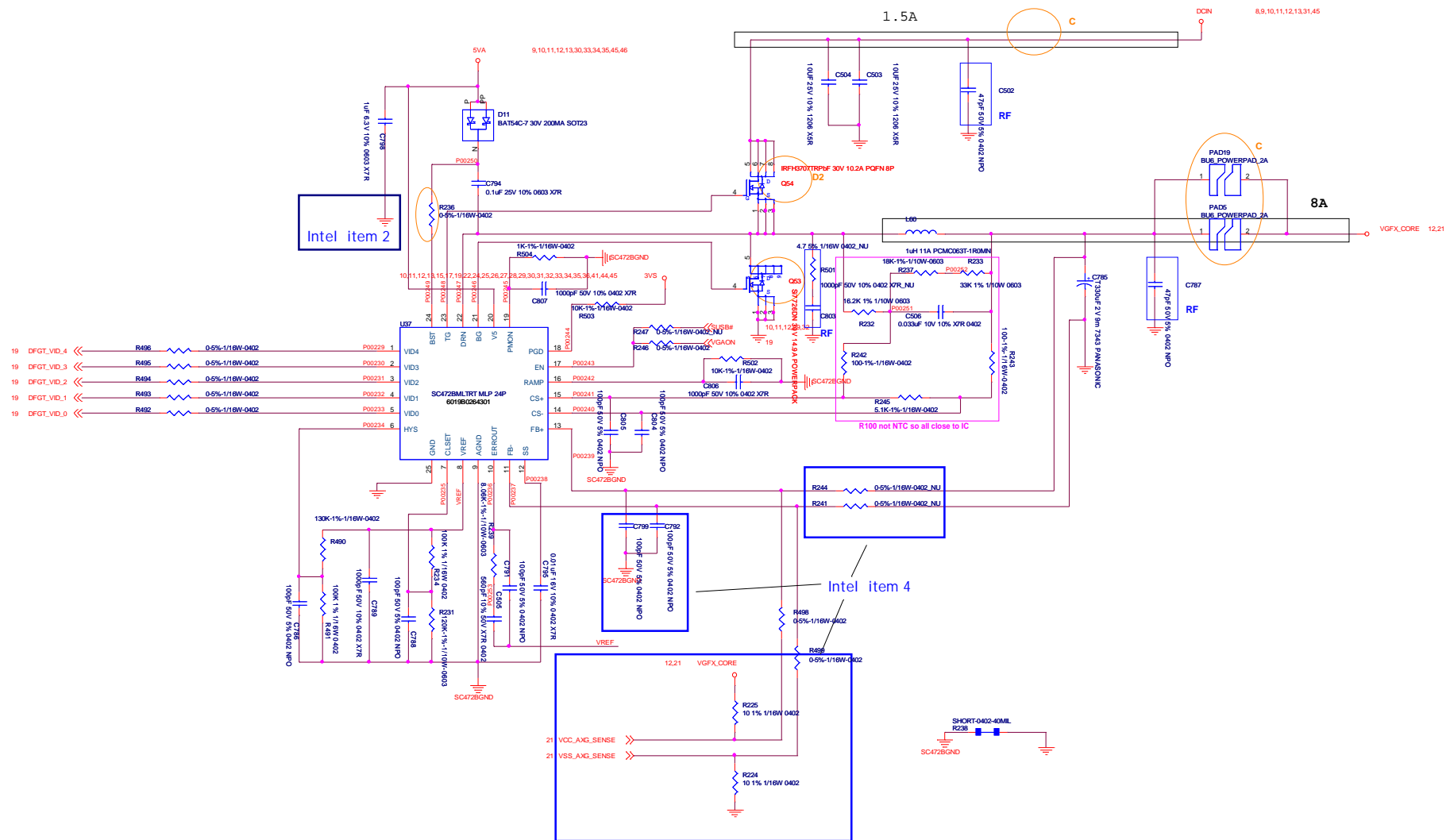
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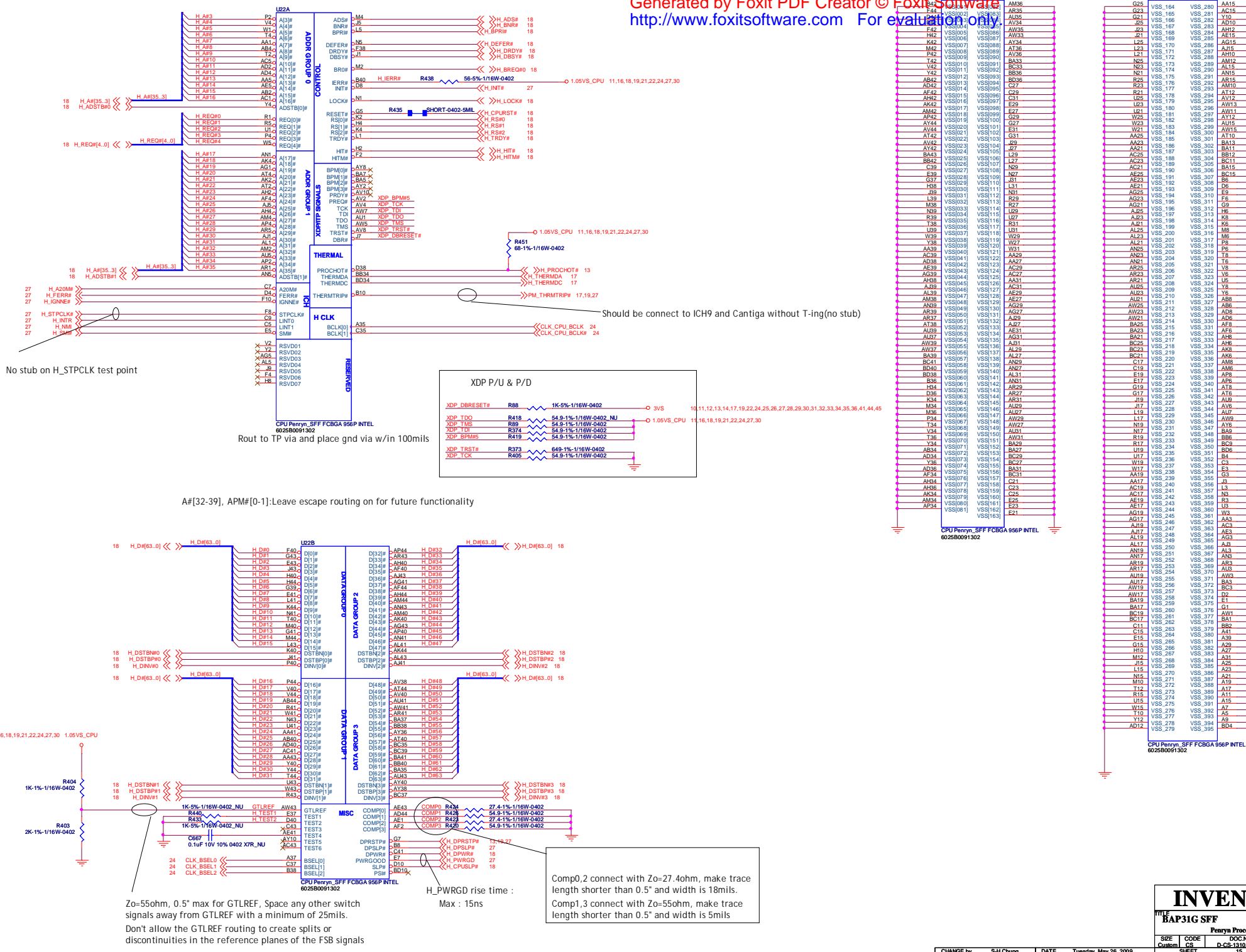
**INVENTEC**

TITLE <b>BAP31G SFF</b>			
Power on latch			
SIZE Custom	CODE CS	DOC. NUMBER D-CS-1310A22B4501-ALG	REV A03
SHEET		12 of	47

CHANGE by	S-H Chung	DATE	Tuesday, May 26, 2009
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ULV Dual-Core : 18A(max)  
ULV Single-Core : 9A(max)

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Power-up peak current : 2.5A (max)  
Steady-state current : 2.5A (max)

Place these inside socket cavity on L8  
(North side secondary)

Place these inside socket cavity on L8  
(South side secondary)

Place these inside socket cavity on L1  
(North side Primary)

Place these inside socket cavity on L1  
(South side Primary)

North side secondary

South side secondary

Route VCCSENSE and VSSSENSE traces  
at 27.4 ohms. Place PU and PD within  
2 inch of CPU

Place these inside socket cavity on L8  
(North side secondary)

160mil

130mA (max)

Close to CPU  
pin B34

Impedance 55 Ohm, W:S= 1:2

Mismatch 25mil

18mil  
7mil space  
25mil space with other

CPU Penryn\_SFF FCBGA 956P INTEL  
6025B0091302

INVENTEC

BAP31G SFF

Penryn Processor(2/2)

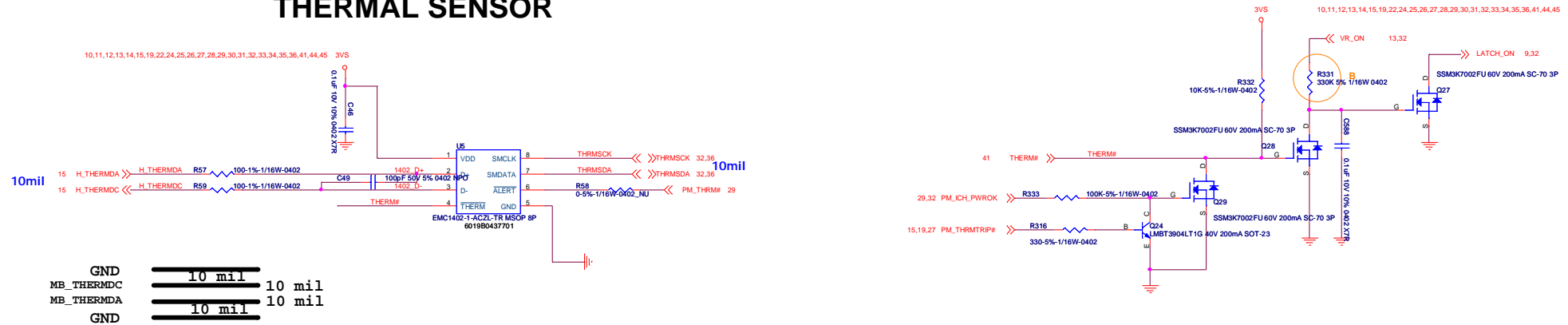
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SHEET	16	47

CHANGE by S-H Chung

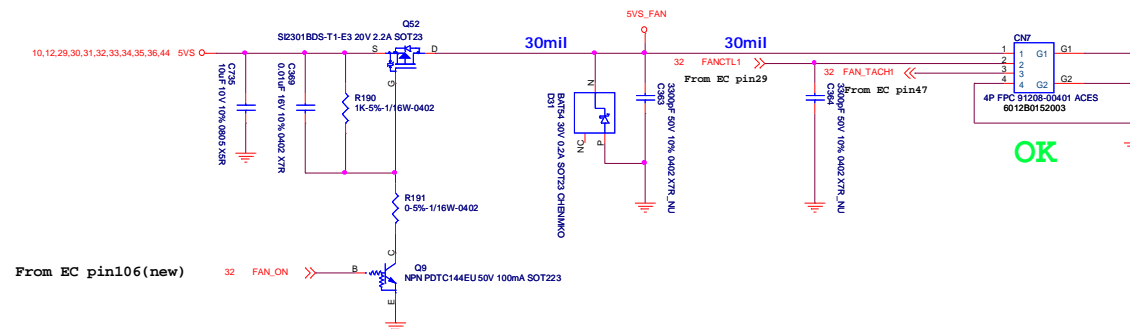
DATE Tuesday, May 26, 2009

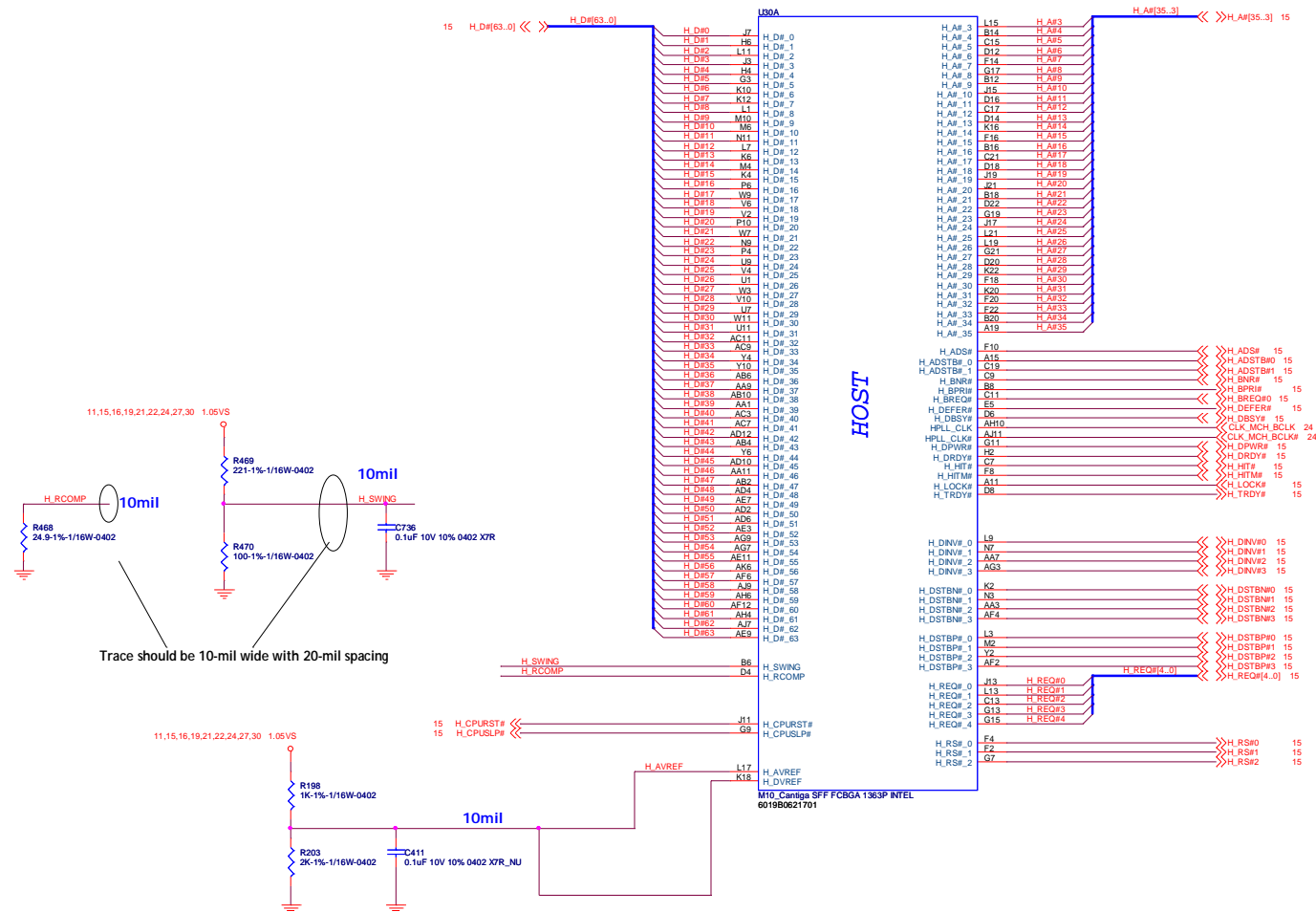


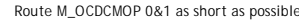
## THERMAL SENSOR



## Fan control



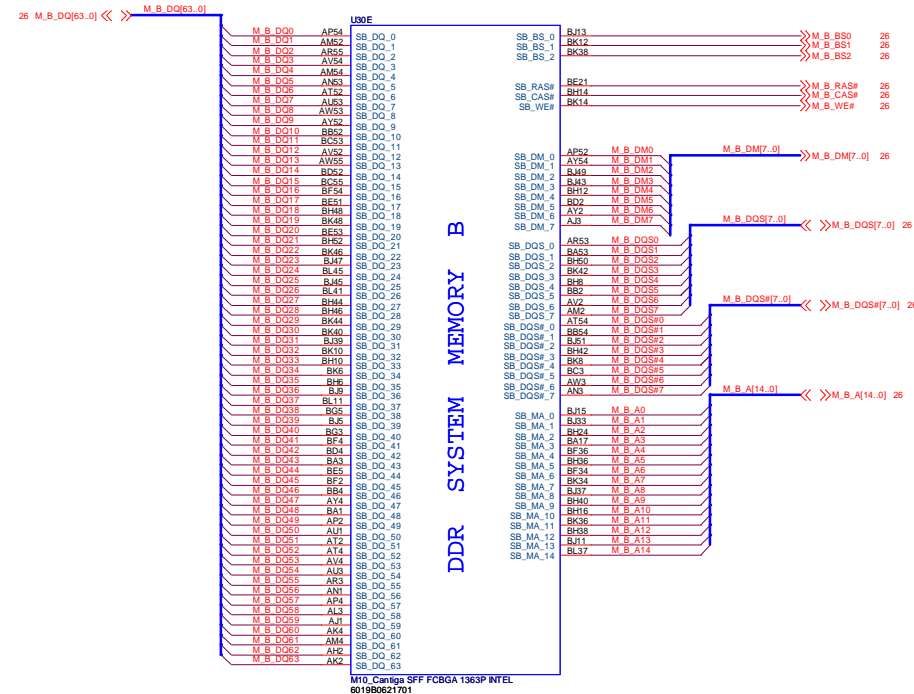
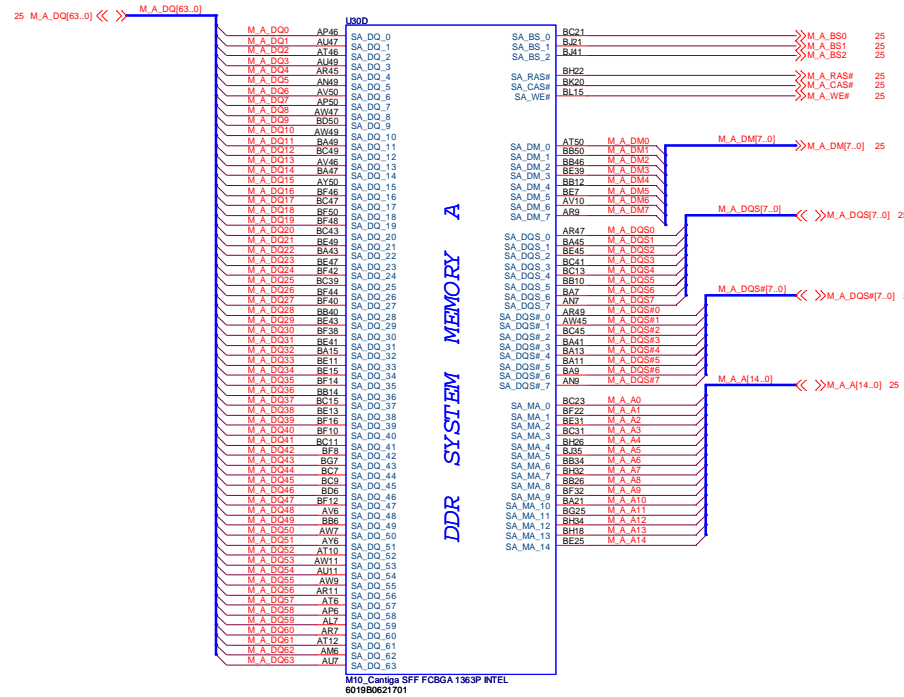




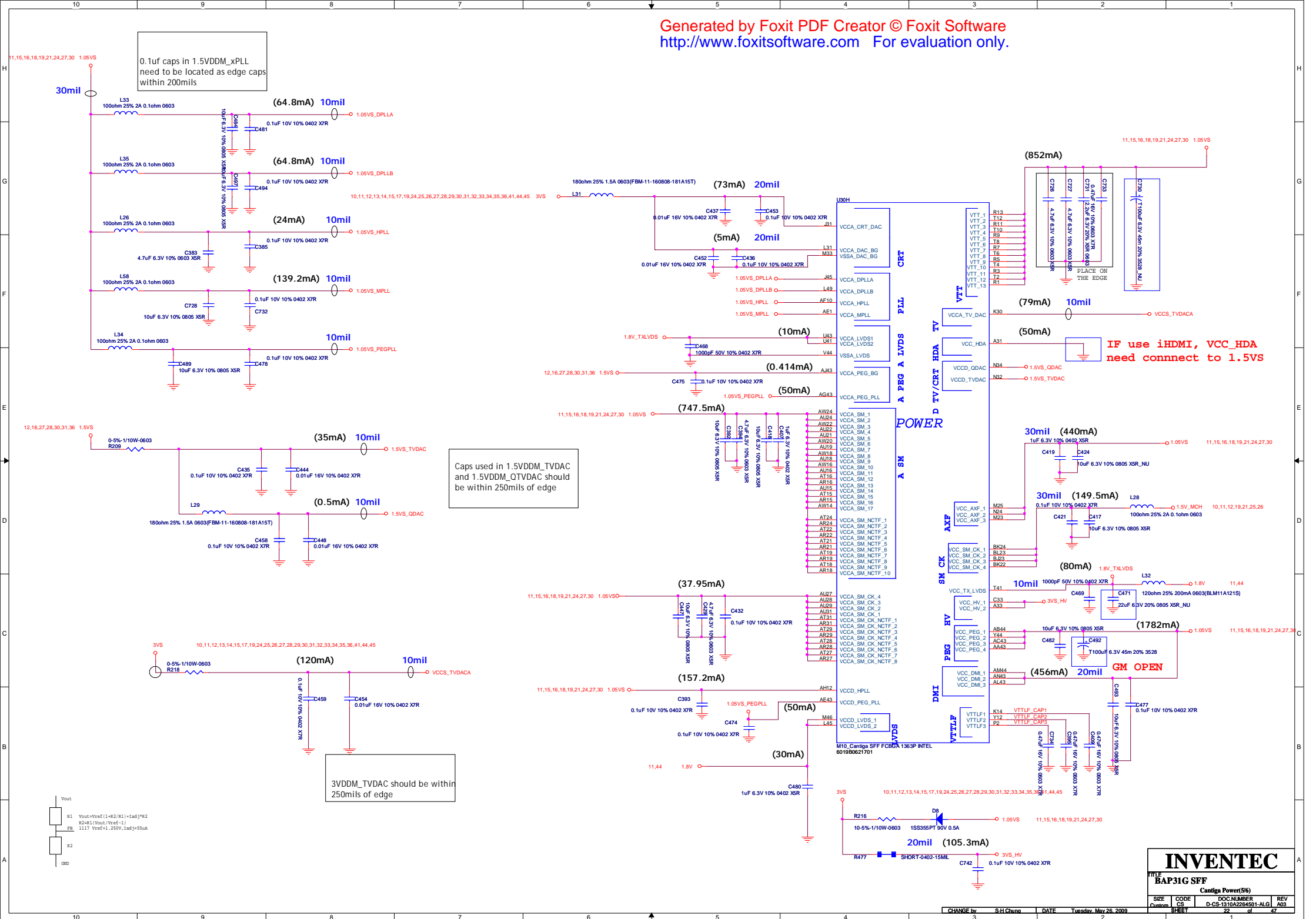
	Low	High
MCH_CFG5	DMix2	DMix4
MCH_CFG6 (ITPM Host I/F)	Enable	Disable(default)
MCH_CFG7 (TLS confidentiality)	With	With no(default)
MCH_CFG9 (PCIe Graphic Lane)	Reverse Lane	Normal Operation
MCH_CFG10 (PCIe loopback)	Enable	Disable(default)
MCH_CFG12 (ALLZ)	Enable	Disable(default)
MCH_CFG13(XOR)	Enable	Disable(default)
MCH_CFG16 (FSB Dynamic ODT)	Dynamic ODT Disable	Dynamic ODT Enable
MCH_CFG19 (DMI Lane Reversal)	Normal	Lanes Reversed
MCH_CFG20	Only Digital Display Port (SDVO/DP/HDMI) or PCIe or is operational (Default)	Digital Display Port (SDVO/DP/HDMI) and PCIe are operating simultaneously via PE port

	LOW	HIGH
<b>SDVO_CTRLDATA</b>	SDVO/HDMD/DP disabled (default)	SDVO/HDMD/DP enabled
<b>L_DDC_DATA</b>	LFP Disabled (default)	LFP Card Present/PCIe disabled
<b>DDPC_CTRLDATA</b>	Digital display (iHDMD/DP) disabled (default)	Digital display (iHDMD/DP) enabled

FILE			
BAP31G SFF			
Cantiga DM1/Graph2(6)			
SIZE	CODE	DOC.NUMBER	
Custom	CS	D-CS-1310A2264501-ALG	
			REV
			A03

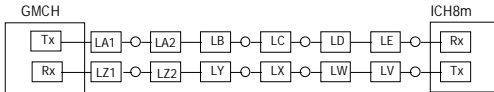
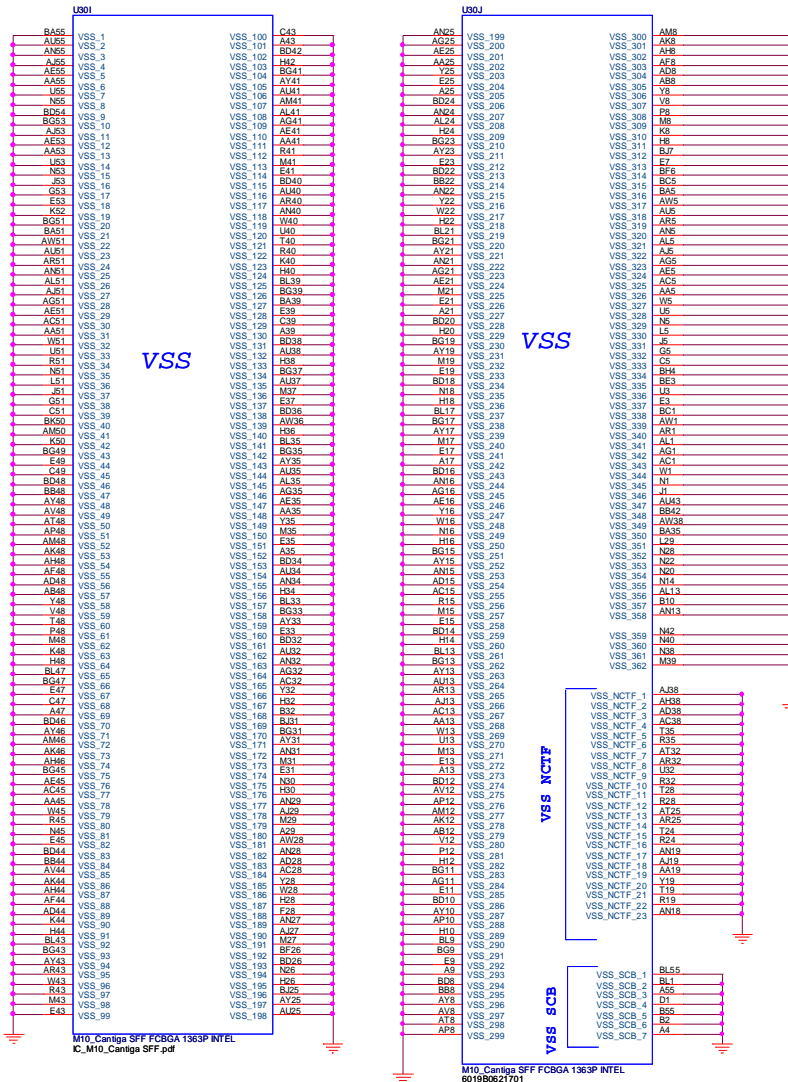






## DMI Routing Guideline

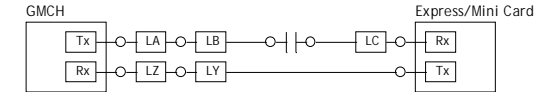
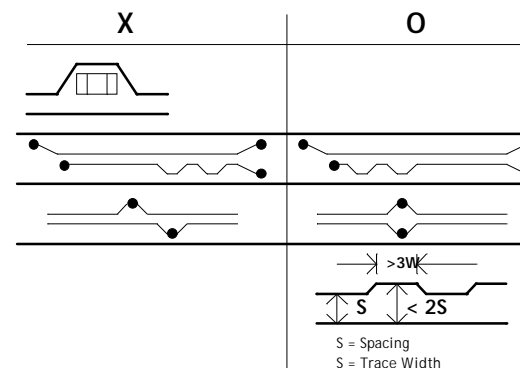
## PCIE Routing Guideline



Breakout/in LA/LZ	Main Route LB/LY	Breakout/in LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV

Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	
Nominal Differential Pair-Pitch	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 22 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	
Trace Length-LA (ICM7m Breakout)	Max = 400 mils	
Trace Length-LB (ICM7m Breakout to AC cap)	Max = 10750 mils	
Trace Length-LC (AC cap to PCIe CN)	Max = 10750 mils	
Trace Length-L1 (LA+LB+LC+LD+LE)	Max = 8000 mils	
Trace Length-LV (ICM7m Breakout)	Max = 400 mils	
Trace Length-LW (ICM7m Breakout to Via2)	Max = 3600 mils	
Trace Length-LX (Via2 to Via3)	Max = 5900 mils	
Trace Length-LY (Via3 to ICH7m Breakout)	Max = 3600 mils	
Trace Length-LZ (ICM7m Breakout)	Max = 400 mils	
Trace Length-L2 (LV+LW+LX+LY+LZ)	Max = 8000 mils	

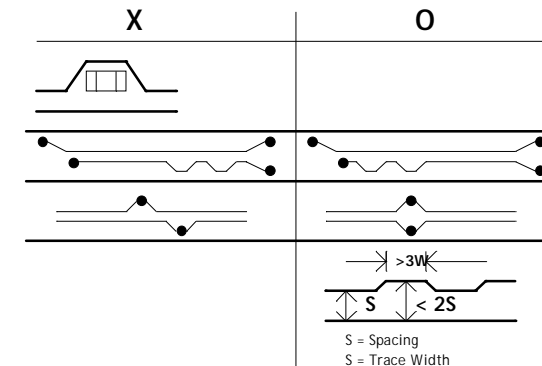
\*\*\* When routing near the edge of their reference plane, trace should maintain at least 40 mils space to the edge of the plane  
\*\*\* Match the trace lengths of the complementary signals within each differential pair to +/- 5 mils



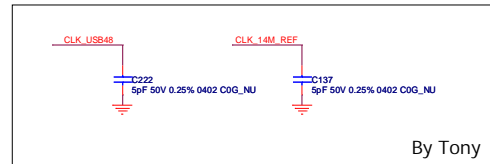
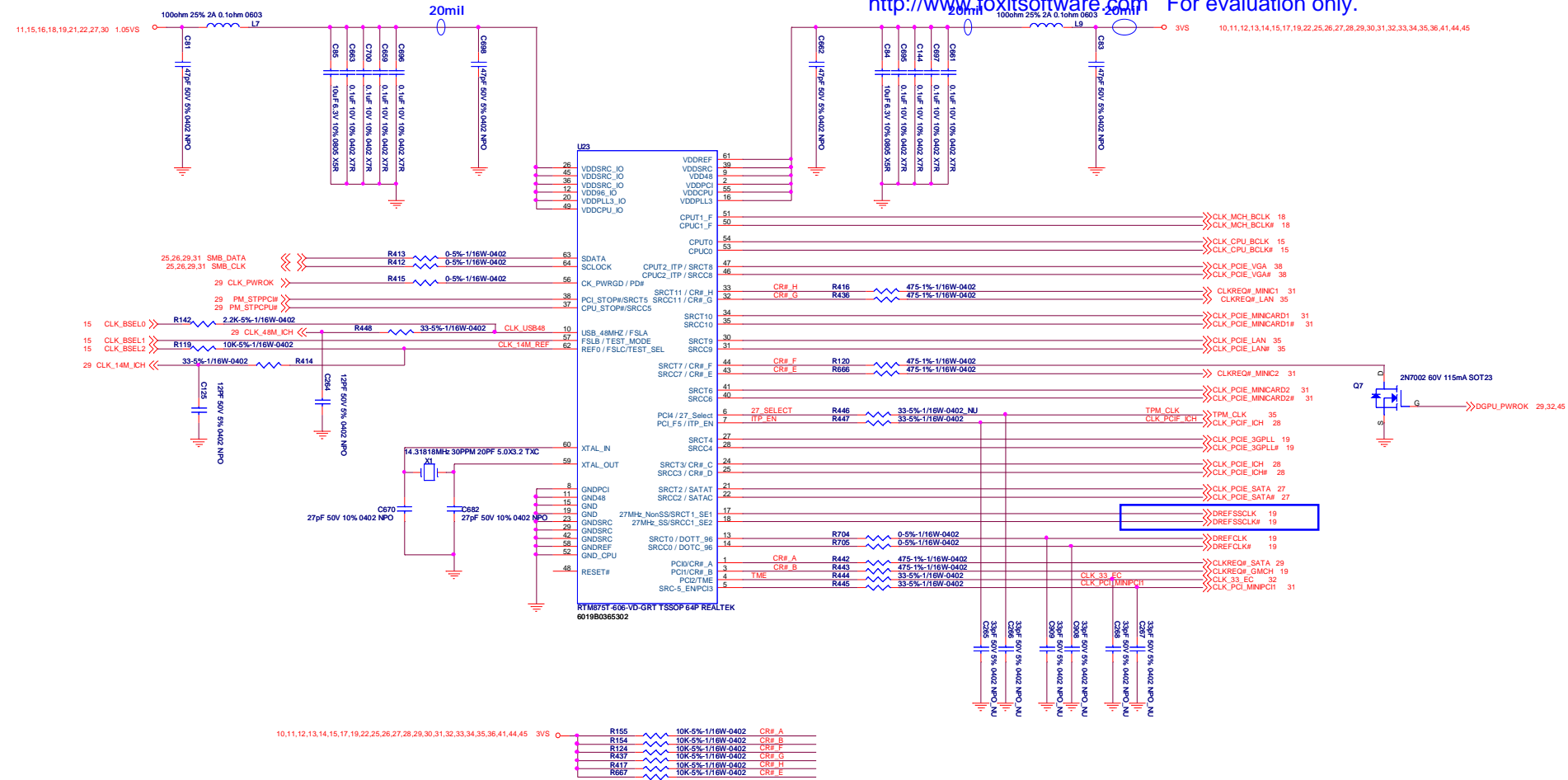
Breakout/in LA/LZ	Main Route LB/LY	Main Route LD/LW	Breakout/in LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip

Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	
Nominal Differential Trace Space	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 20 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	
Trace Length-LA (ICM7m Breakout)	Max = 400 mils	
Trace Length-LB (ICM7m Breakout to AC cap)	Max = 10750 mils	
Trace Length-LC (AC cap to PCIe CN)	Max = 10750 mils	
Trace Length-L1 (LA+LB+LC)	Max = 12000 mils	
Trace Length-LY (PCIe CN to ICH7m Breakout)	Max = 11950 mils	
Trace Length-LZ (ICM7m Breakout)	Max = 400 mils	
Trace Length-L2 (LY+LZ)	Max = 12000 mils	

\*\*\* When routing near the edge of their reference plane, trace should maintain at least 40 mils space to the edge of the plane  
\*\*\* Match the trace lengths of the complementary signals within each differential pair to +/- 5 mils







FSA	FSB	FSC	FSB CLOCK FREQUENCY	HOST CLOCK FREQUENCY
1	1	0	667	166
0	1	0	800	200
0	0	0	1067	266 ★

```
ITP_EN = 0
SRC8/SRC8#
ITP_EN = 1
ITP/ITP#
```

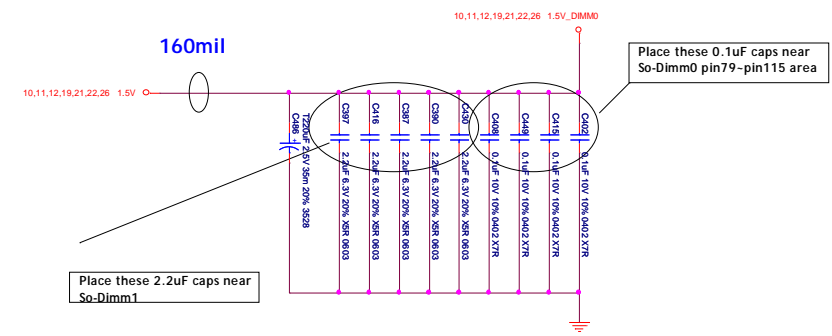
```
27_SELECT = 0
Dot96/ LCD_SS /SE
27_SELECT = 1
SRC0/ 27MHz
```

By Tony

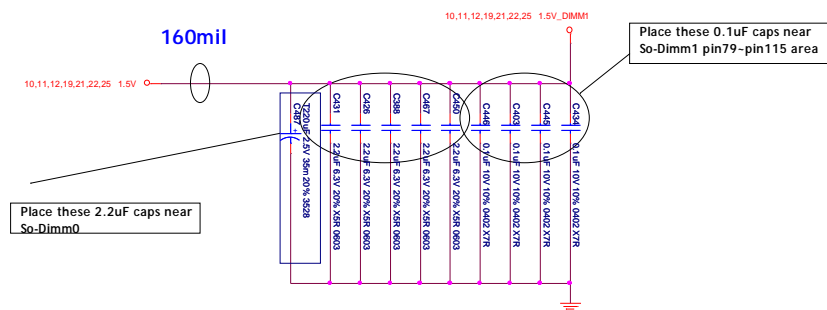
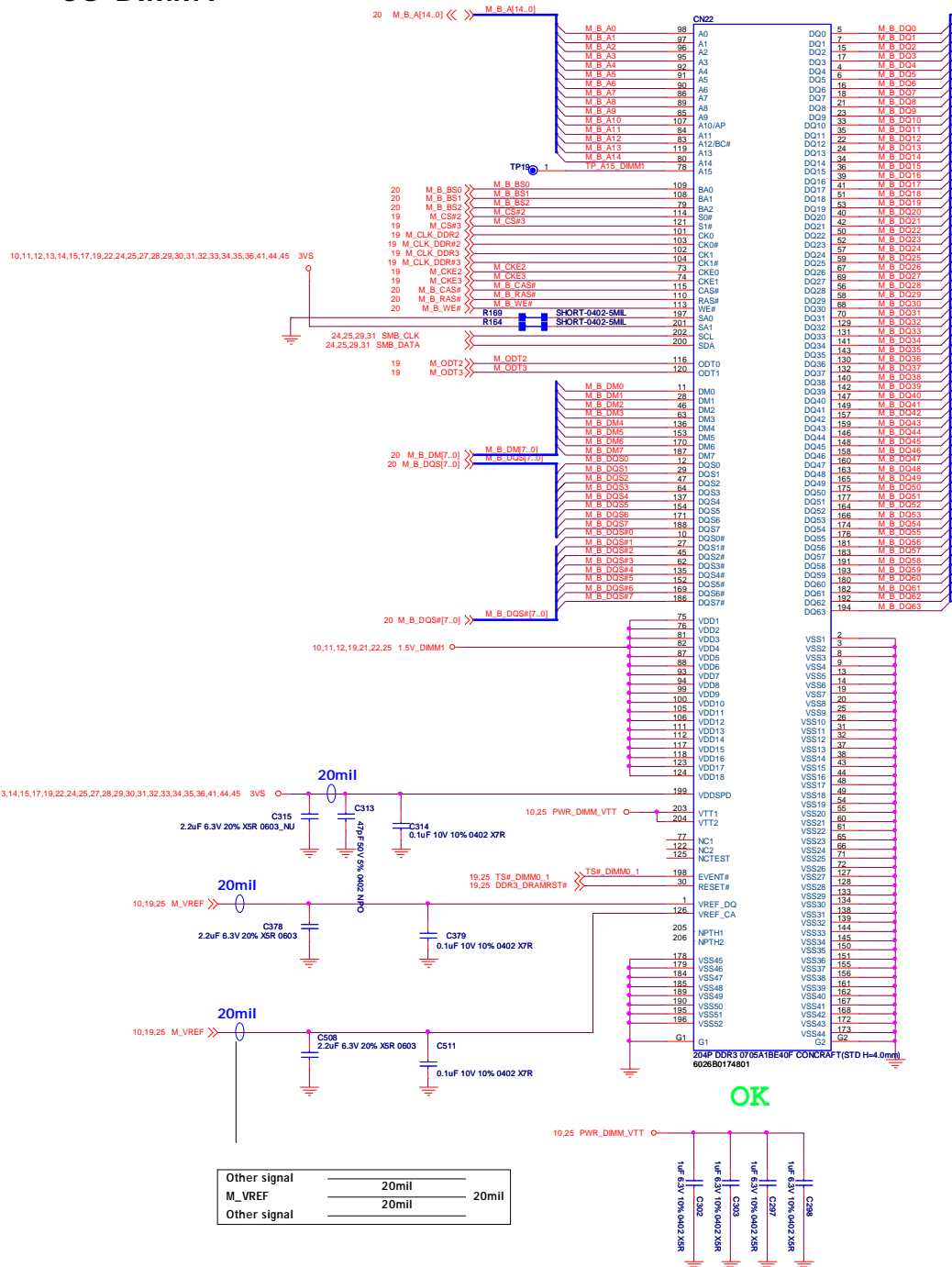
CR#_A:	Byte 5 bit 6=0--->SRC0 bit 6=1--->SRC2	BIT 7=1 (Enable)
CR#_C:	Byte 5 bit 2=0--->SRC0 bit 2=1--->SRC2	BIT 3=1 (Enable)
CR#_B:	Byte 5 bit 4=0--->SRC1 bit 4=1--->SRC4	BIT 5=1 (Enable)
CR#_D:	Byte 5 bit 0=0--->SRC1 bit 0=1--->SRC4	BIT 1=1 (Enable)
CR#_E:	SRC6 (Byte 6)	BIT 7=1 (Enable)
CR#_F:	SRC8 (Byte 6)	BIT 6=1 (Enable)
CR#_G:	SRC9 (Byte 6)	BIT 5=1 (Enable)
CR#_H:	SRC10 (Byte 6)	BIT 4=1 (Enable)

<b>INVENTEC</b>	
<small>TITLE</small>	<b>BAP31G SFF</b>





# SO-DIMM1

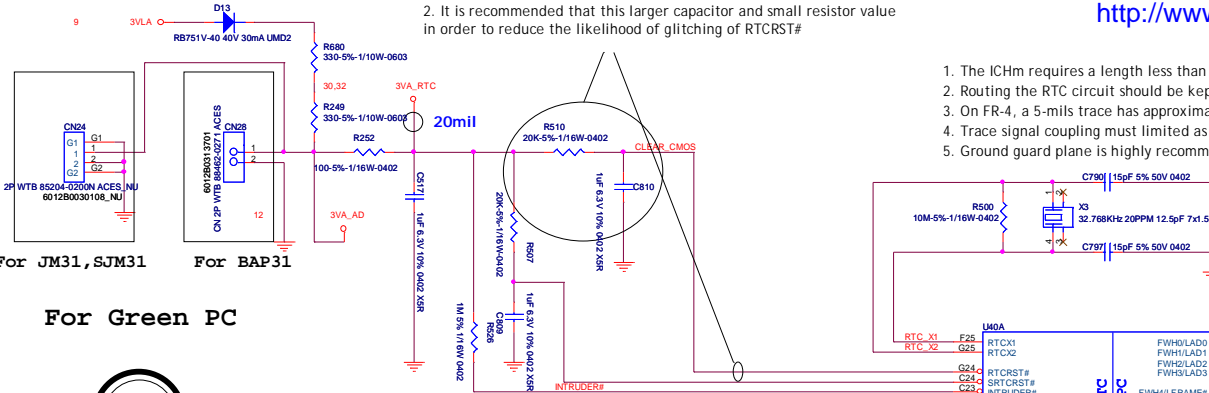


## RTC Circuit

1. RC delay time should be in the range of 18-25ms
2. It is recommended that this larger capacitor and small resistor value in order to reduce the likelihood of glitching of RTRST#

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1. The ICHM requires a length less than 1 inch on each branch ( from crystal's terminal to RTCXn ball)
2. Routing the RTC circuit should be kept simple to simplify the trace length measurement and increase accuracy on calculating trace capacitances
3. On FR-4, a 5-mils trace has approximately 2pF per inch
4. Trace signal coupling must limited as much as possible by avoiding the routing of adjacent PCI signals close to RTCX1 and RTCX2
5. Ground guard plane is highly recommended

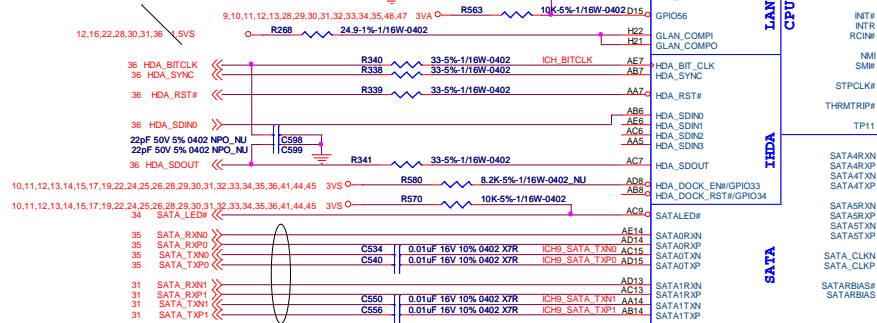
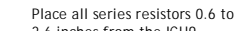


For Green PC

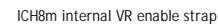
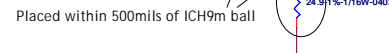


CABLE,ROUND,3POS,75mm,I,RTC\_NU  
6027B0066801

**RTC Battery Life :**  
 $220\text{mAh}(220000\mu\text{Ah}) / 6\mu\text{A} = 4.2 \text{ year}$

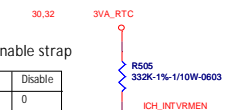


Distance between the ICH9-M and cap on the "P" signal should be identical distance between the ICH9-M and cap on the "N" signal for same pair.

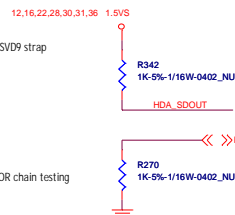


	Enable	Disable
INTVRMEN	1(Default)	0

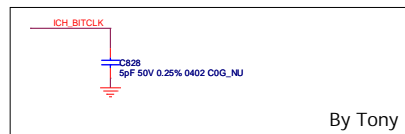
Internal VRM enabled for  
VccSus1\_05, VccSus1\_5,  
VccCL1\_5, VccLAN1\_05 and  
VccCL1\_05



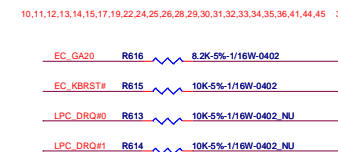
ACZ\_SDATAOUT strap functionality base on RSVD9 strap  
XOR chain entrance (RSVD9 pulled low)  
PCIE port config bit 1(RSVD9 not pulled low)



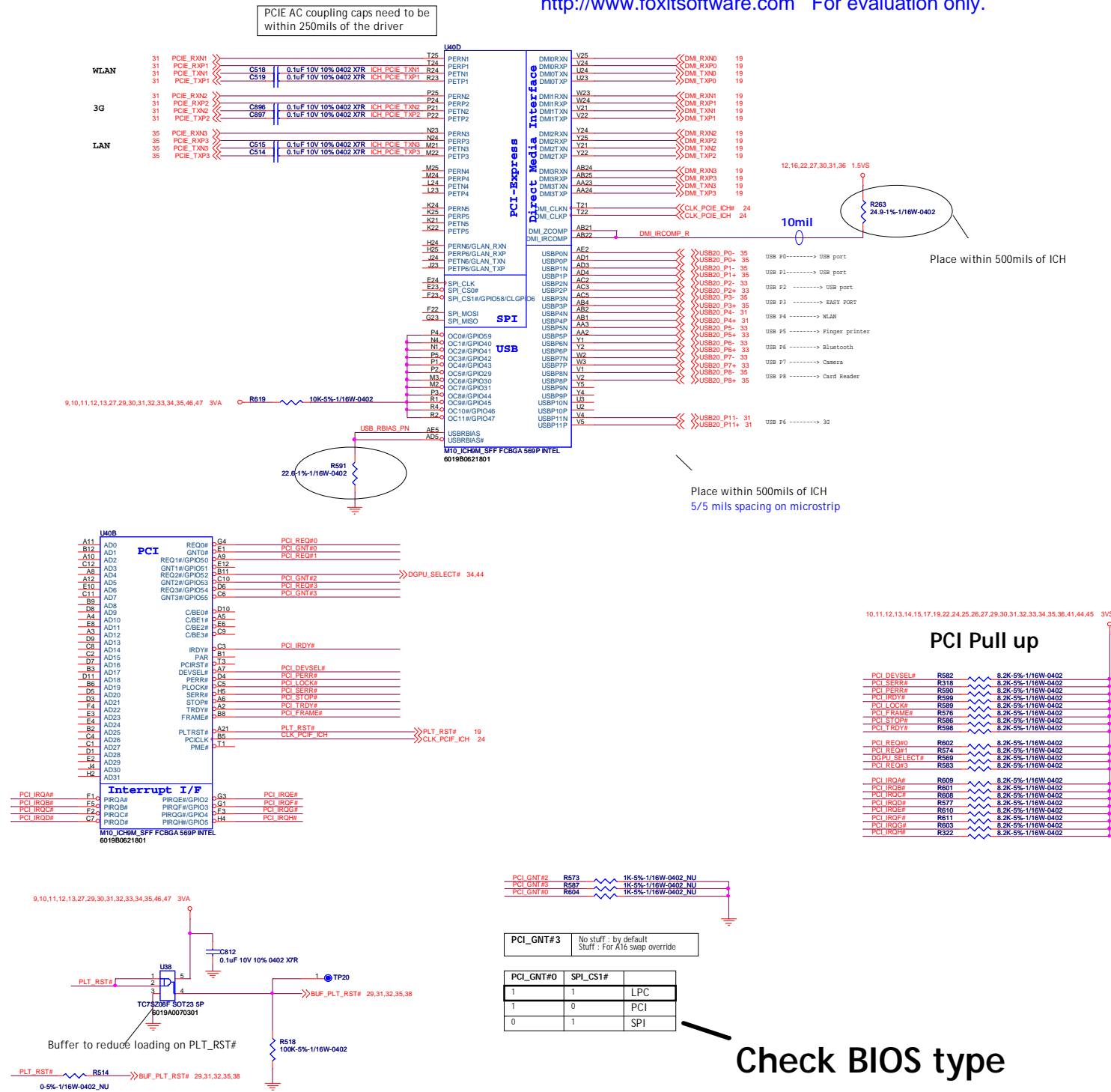
XOR Chain Entrance Strap - to be updated		
ICH_TP3	HDA_SDOUT	Description
0	0	ESVD
0	1	Enter XOR Chain
1	0	Normal Operation (Default)
1	1	Set PCIE port config bit 1



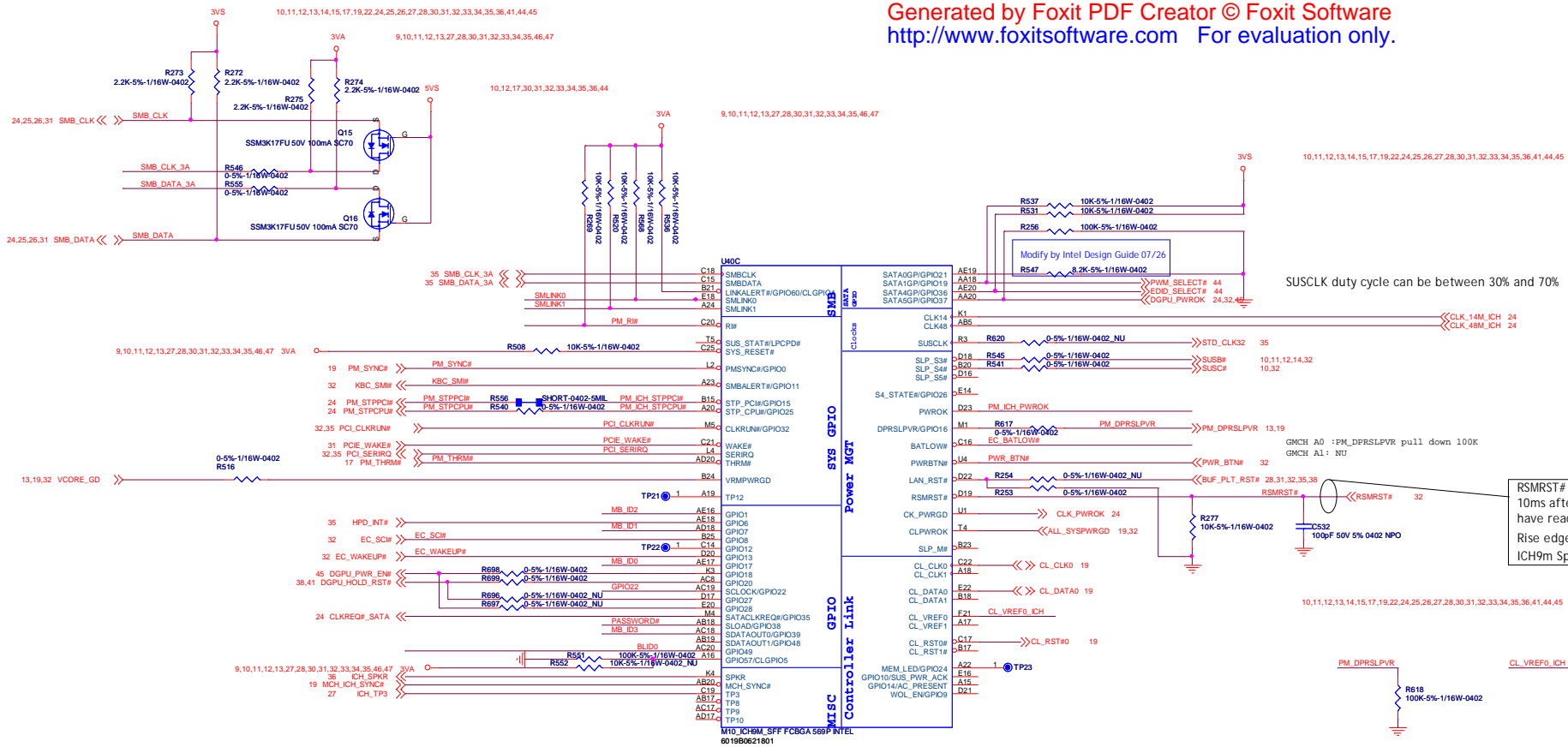
By Tony



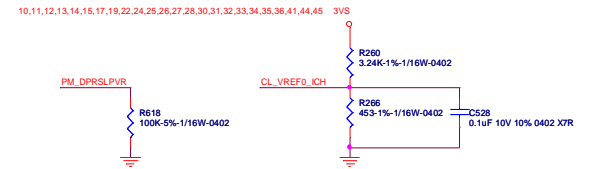
<b>INVENTEC</b>			
TITLE <b>BAP31G SFF</b>			
<b>ICH9M CPU/IDE/SATA (1/4)</b>			
SIZE Custom	CODE CS	DOC.NUMBER D-CS-1310A2264501-ALG	REV A03
SHEET		27	of 47



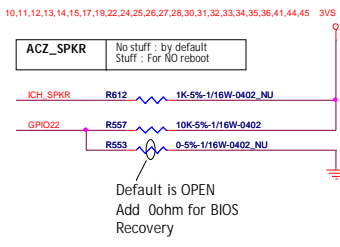
## Check BIOS type



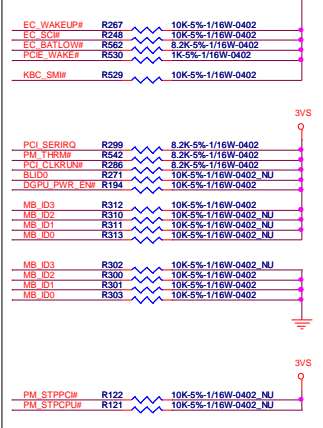
<p>RSMRST# should go high no sooner than 10ms after both Vccsus3_3 and Vccsus1_5 have reached their nominal voltage</p> <p>Rise edge : 1~2us</p> <p>ICH9m Spec : less 50us</p>
--



ICH9m strap

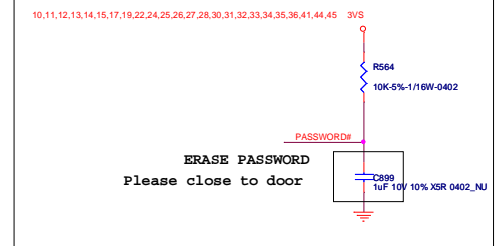


PMU P/U  
9,10,11,12



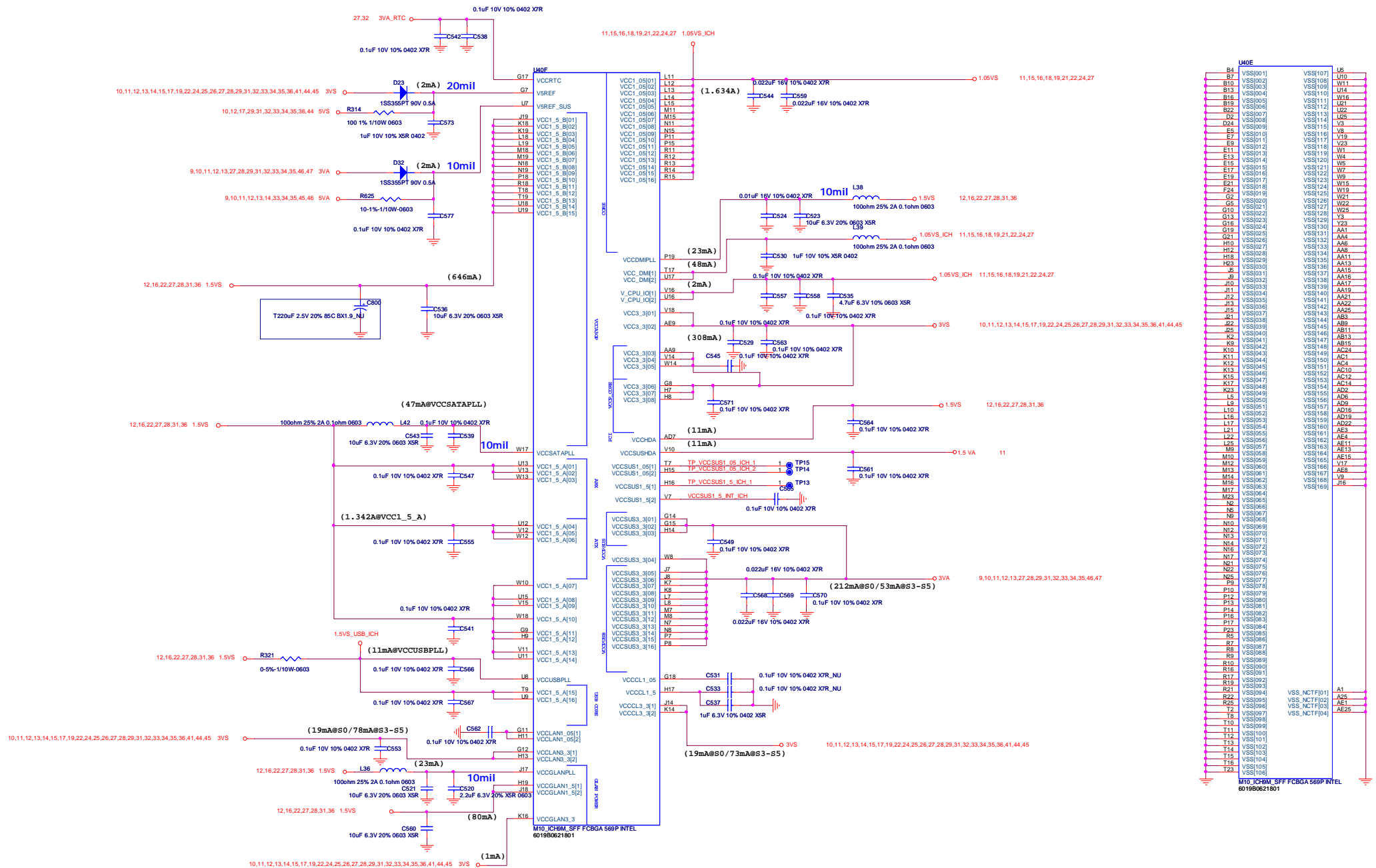
BIOS ID setting				
Project	MB_ID3	MB_ID2	MB_ID1	MB_ID0
JM31 (UMA)	1	1	1	1
SJM31 (UMA)	1	1	1	0
BAP31 (UMA)	1	1	0	1
BAP41 (UMA)	1	1	0	0
BAP51 (UMA)	1	0	1	1
JM31 (dGPU)	1	0	1	0
SJM31 (dGPU)	1	0	0	1
BAP31 (dGPU)	1	0	0	0
BAP41 (dGPU)	0	1	1	1
BAP51 (dGPU)	0	1	1	0
	0	1	0	1
	0	1	0	0
	0	0	1	0
	0	0	0	1
	0	0	0	0

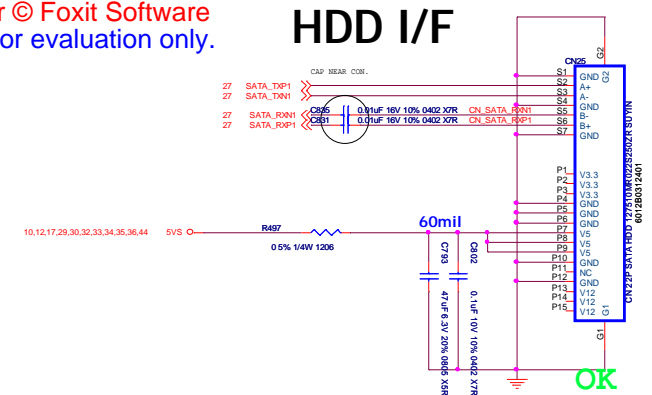
PASSWORD CLEAR

**INVENTEC**

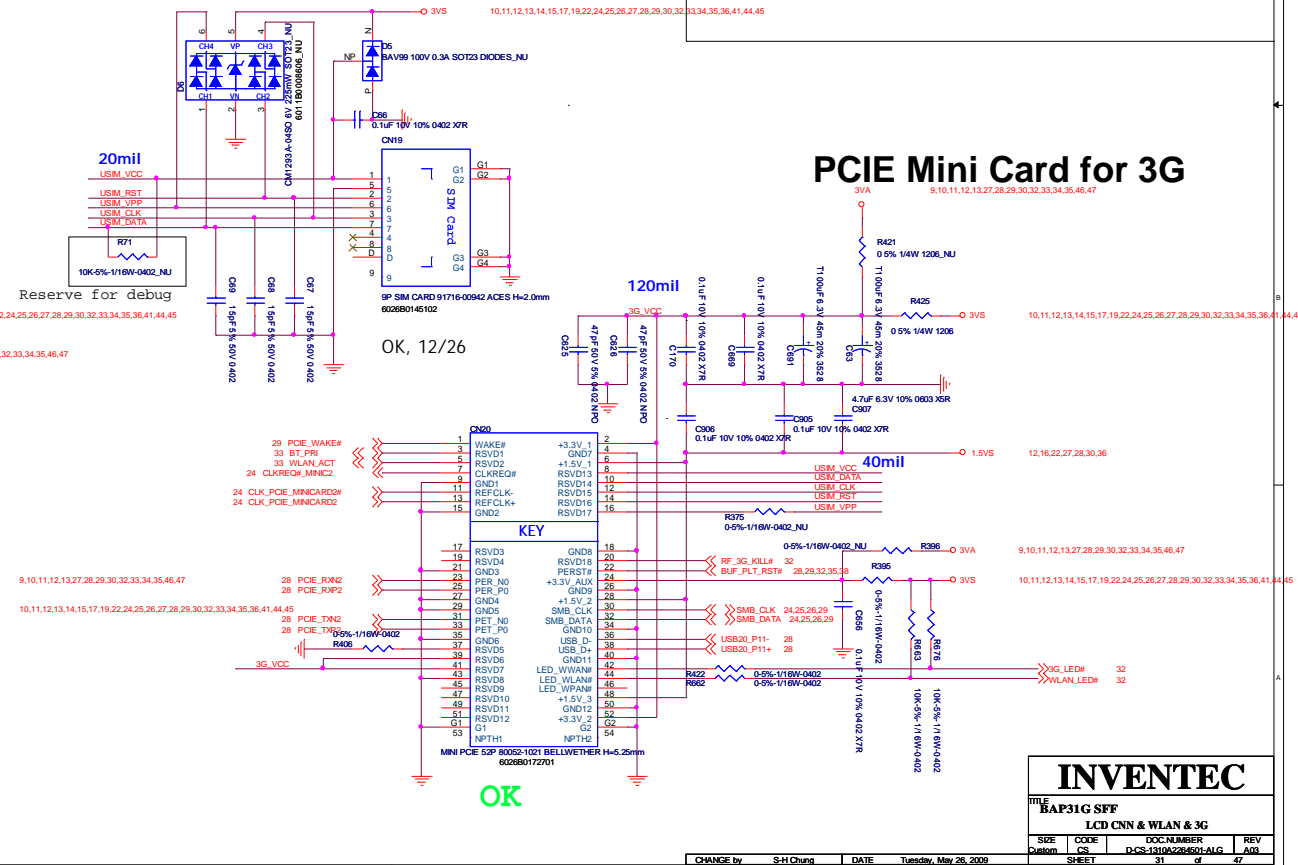
**TITLE**  
**BAP31G SFF**

ICH9M GPIO(3/4)			
SIZE	CODE	DOC.NUMBER	REV
Custom	CS	D-CS-1310A2264501-ALG	A03
SHEET		29	of 47

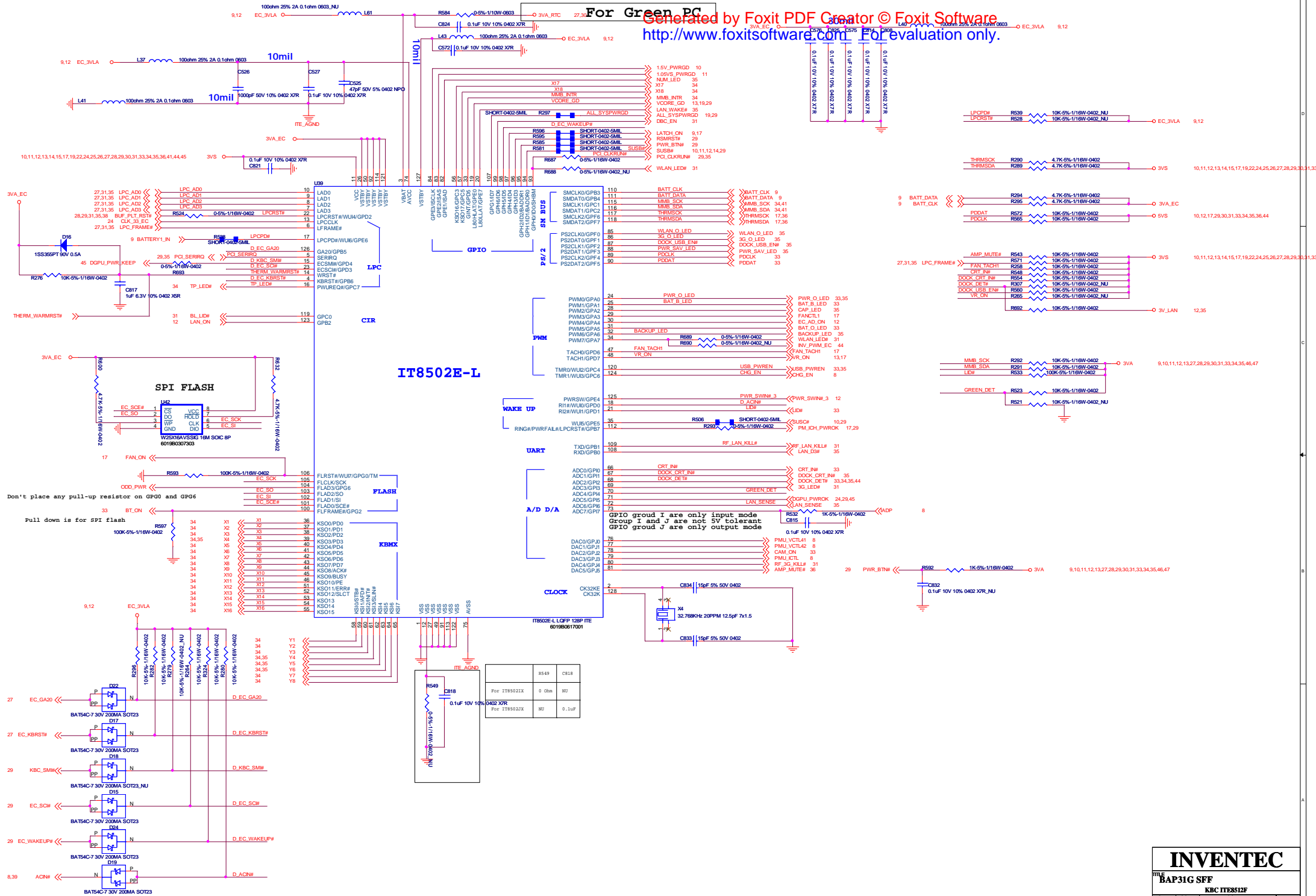




## PCIE Mini Card for 3G



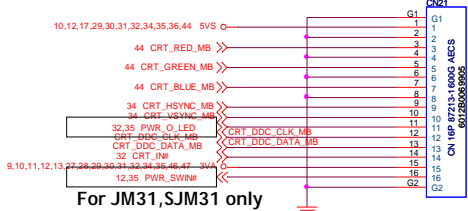






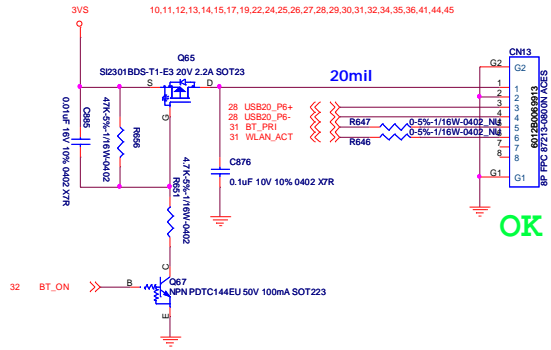
VGA Board CN

(CRT+ PWR SW)



OK

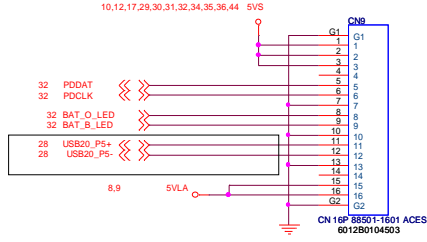
Bluetooth CON.



OK

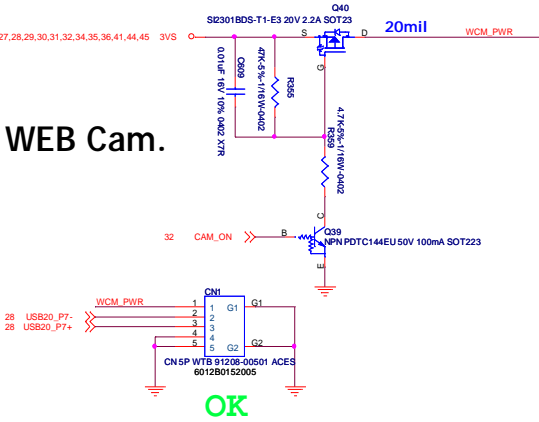
GLIDE PAD Board

For BAP31 only



For All Model

WEB Cam.

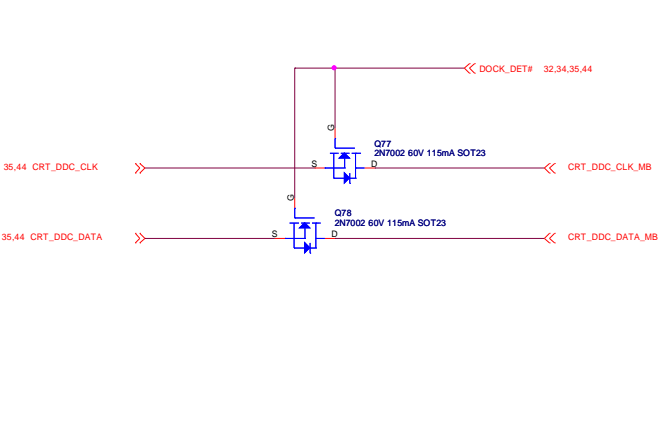


OK

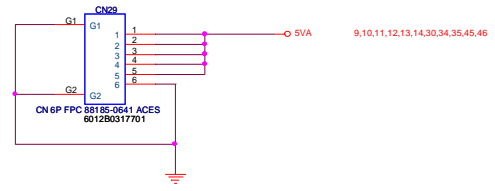
For All Model

AUDIO Board CN

(Audio JACK+1USB)



OK



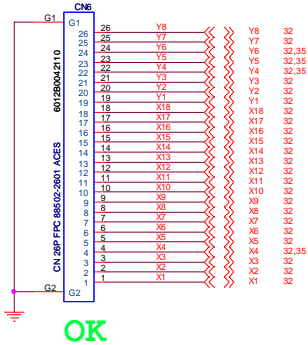
INVENTEC

BAP31G SFF

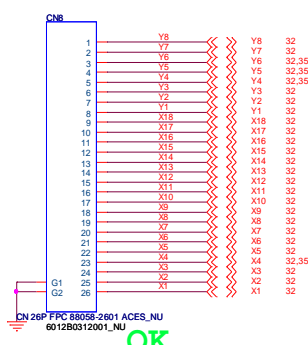
Daughter Connector

SIZE	CODE	DOC NUMBER	REV
Custom	C3	D-CS-1310A2268501-ALG	A03
SHEET	33	47	

## To K/B(For All Model)



## To K/B(No Use)



## GP lock Button / LED(FOR SJM31)



## GP lock Button / LED(FOR BAP31)

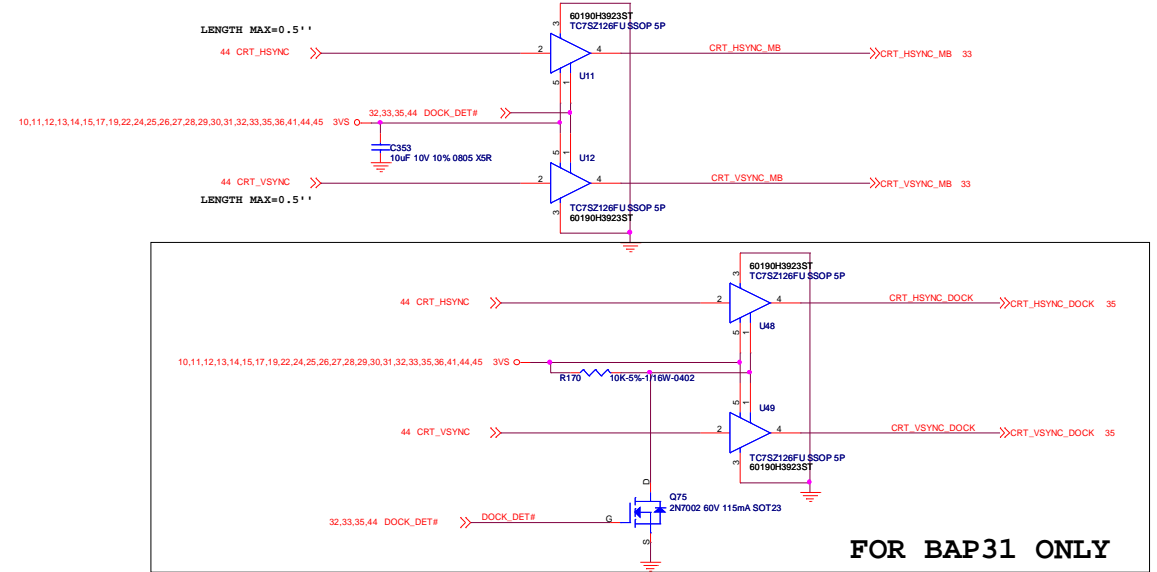
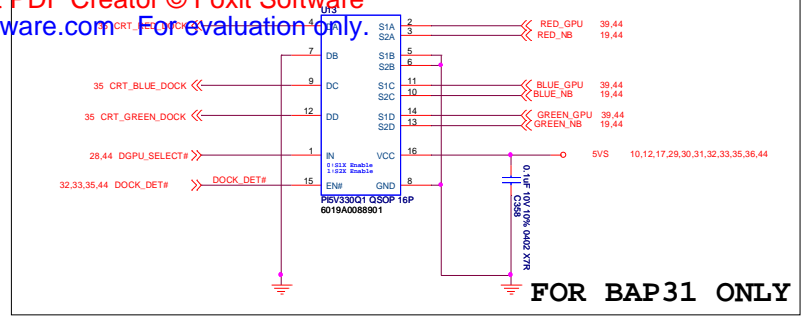


## GP lock Button / LED(FOR JM31)

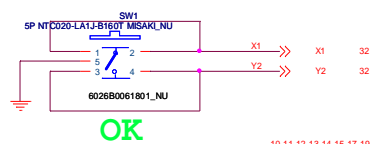


R284  
120 ohm for JM31, BAP31  
470 ohm for SJM31

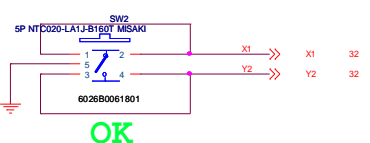
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http://www.foxitsoftware.com For evaluation only.



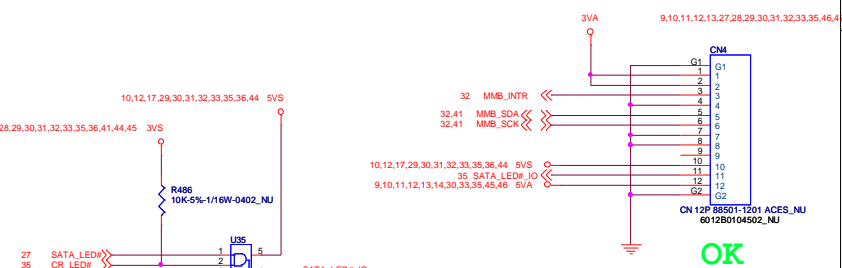
## SW (No Use)



## SW (FOR All Model)



## SW Sensor BOARD(For JM31,SJM31)



## INVENTEC

TITLE			
BAP31G SFF			
BAP			
SIZE	CODE	DOC NUMBER	REV
Custom	C3	D-CS-1310A2268501-ALG	A03
SHEET		34	47

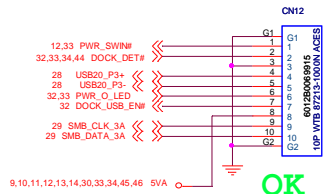
CHANGE by S.H.Chung DATE Tuesday, May 26, 2009

# For BAP31(EASY/B)

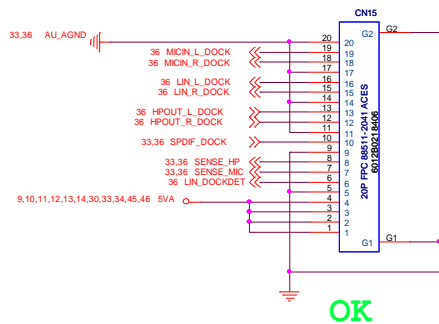
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http://www.foxitsoftware.com For evaluation only.

## SSD I/F For All Model

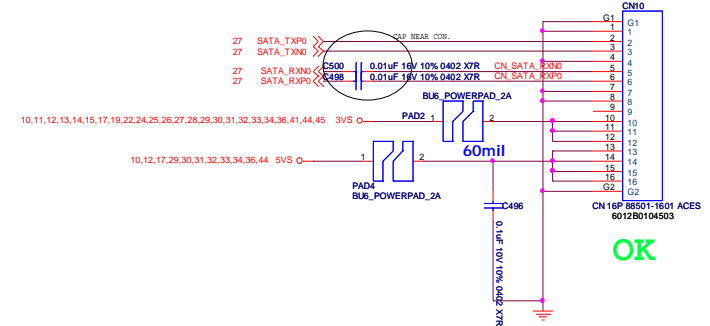
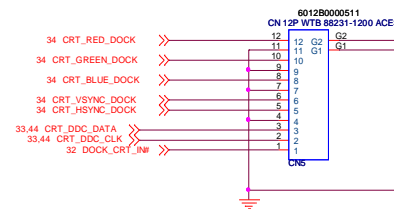
### MB(USB) TO EASY/B For BAP31



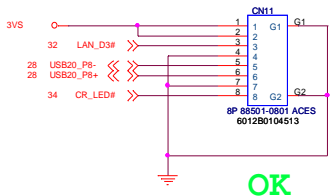
### MB(AUDIO) TO EASY/B For BAP31



### MB(RGB) TO EASY/B For BAP31

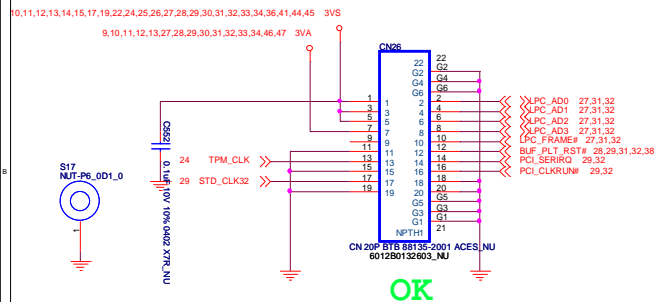


## Card Reader BOARD CN For All Model



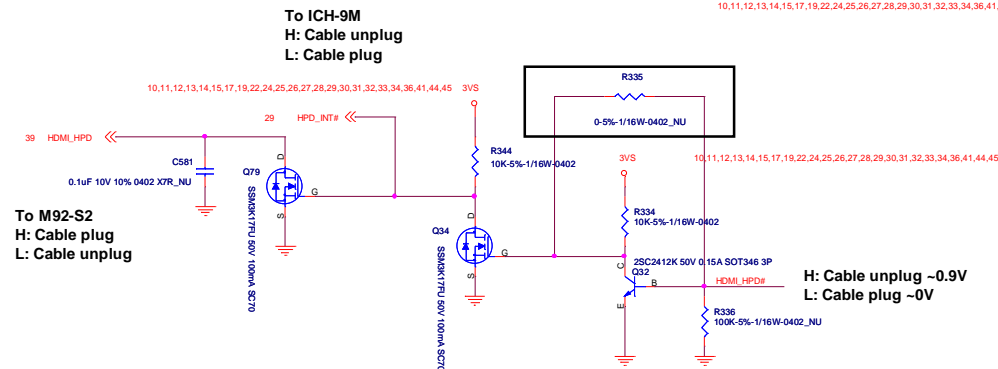
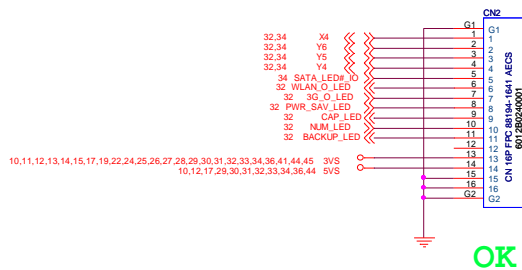
## NO NEED

### TPM CN

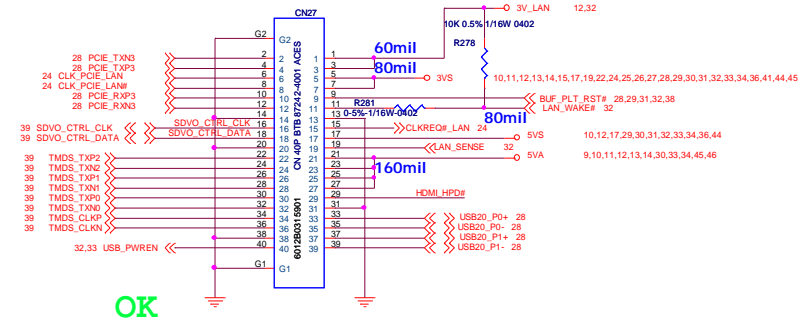


## For BAP31

### SW/B CN

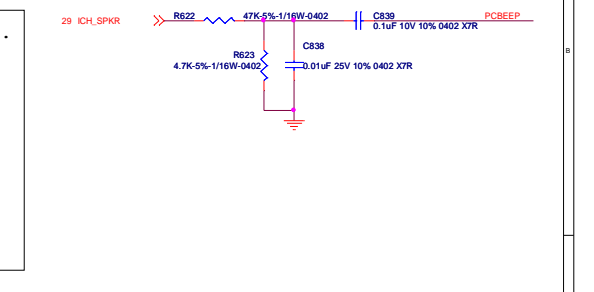
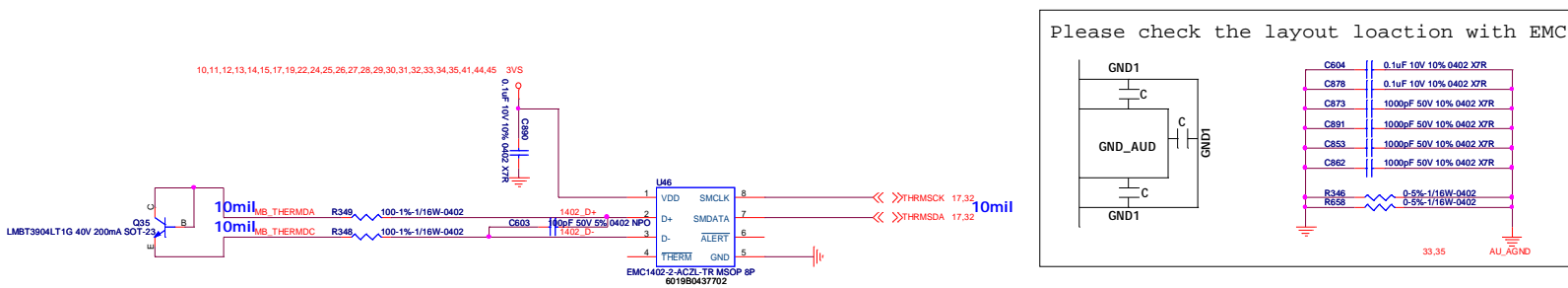
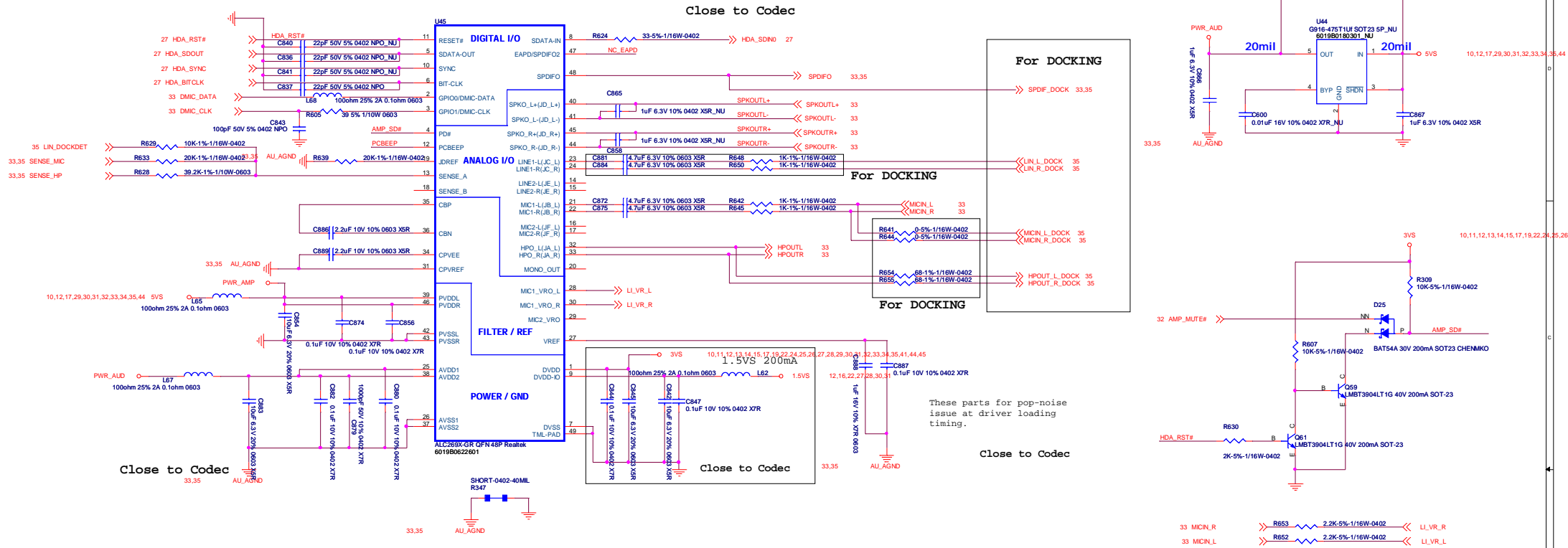


## USB Board CN (LAN+HDMI+2USB) For All Model



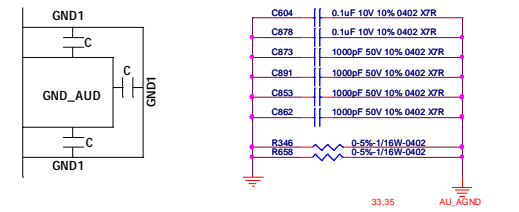
## INVENTEC

TITLE		BAP31G SFF	
SIZE		CODE	
Custom		D-CS-1310A2268501-ALG	
SHEET		REV	
47		A03	



GND		
	10 mil	
MB_THERMDC		10 mil
MB_THERMDA		10 mil
	10 mil	
GND		

Please check the layout loaction with EMC.



These parts for pop-noise  
issue at driver loading  
timing.

Close to Codec

## Close to Codec

For DOCKING

For DOCKING

For DOCKING

Close to Codec

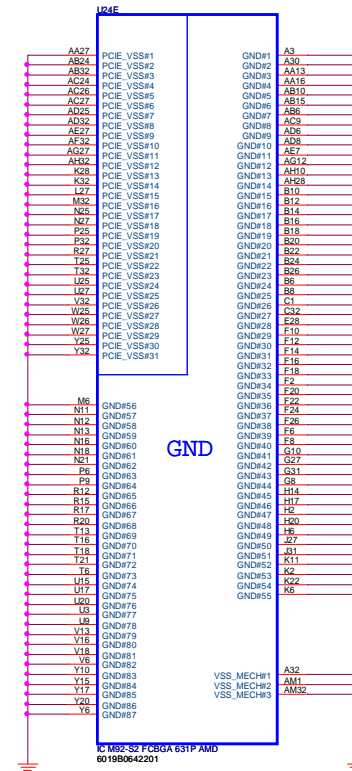
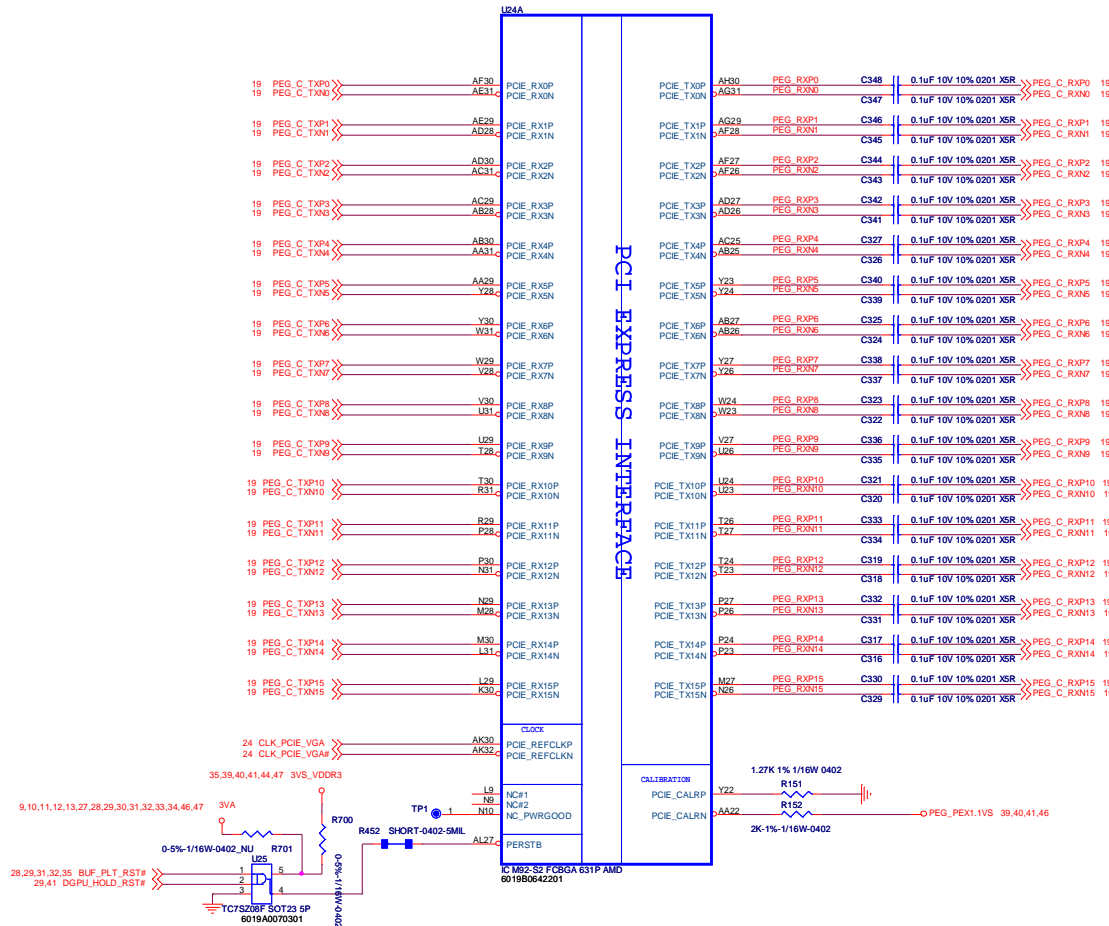
## Close to Codec

**INVENTEC**

TITLE			
BAP31G SFF			
Audio Codec			
SIZE	CODE	DOC.NUMBER	REV
Custom	CS	D-CS-1310A2264501-ALG	A03
SHEET		36	of 47

BLANK

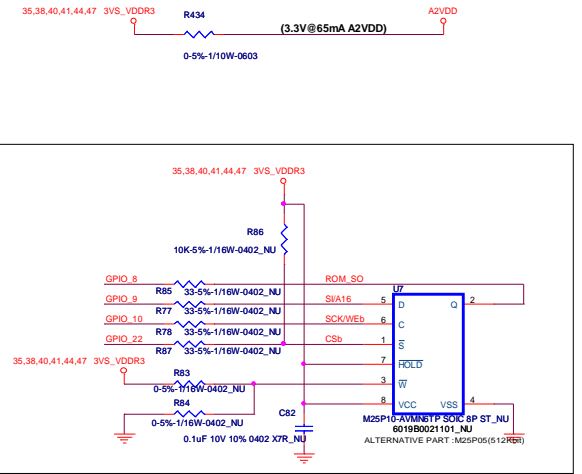
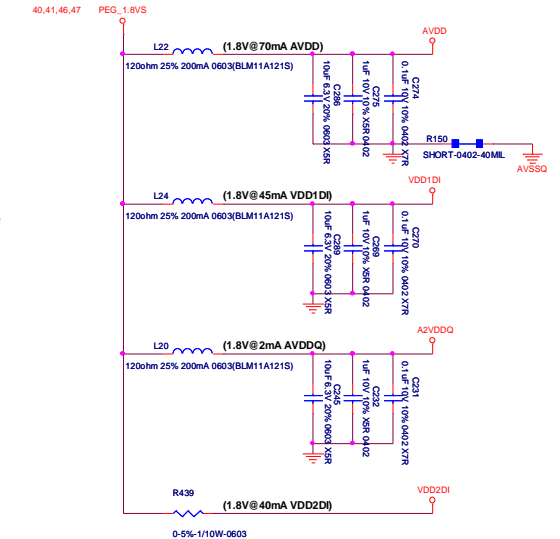
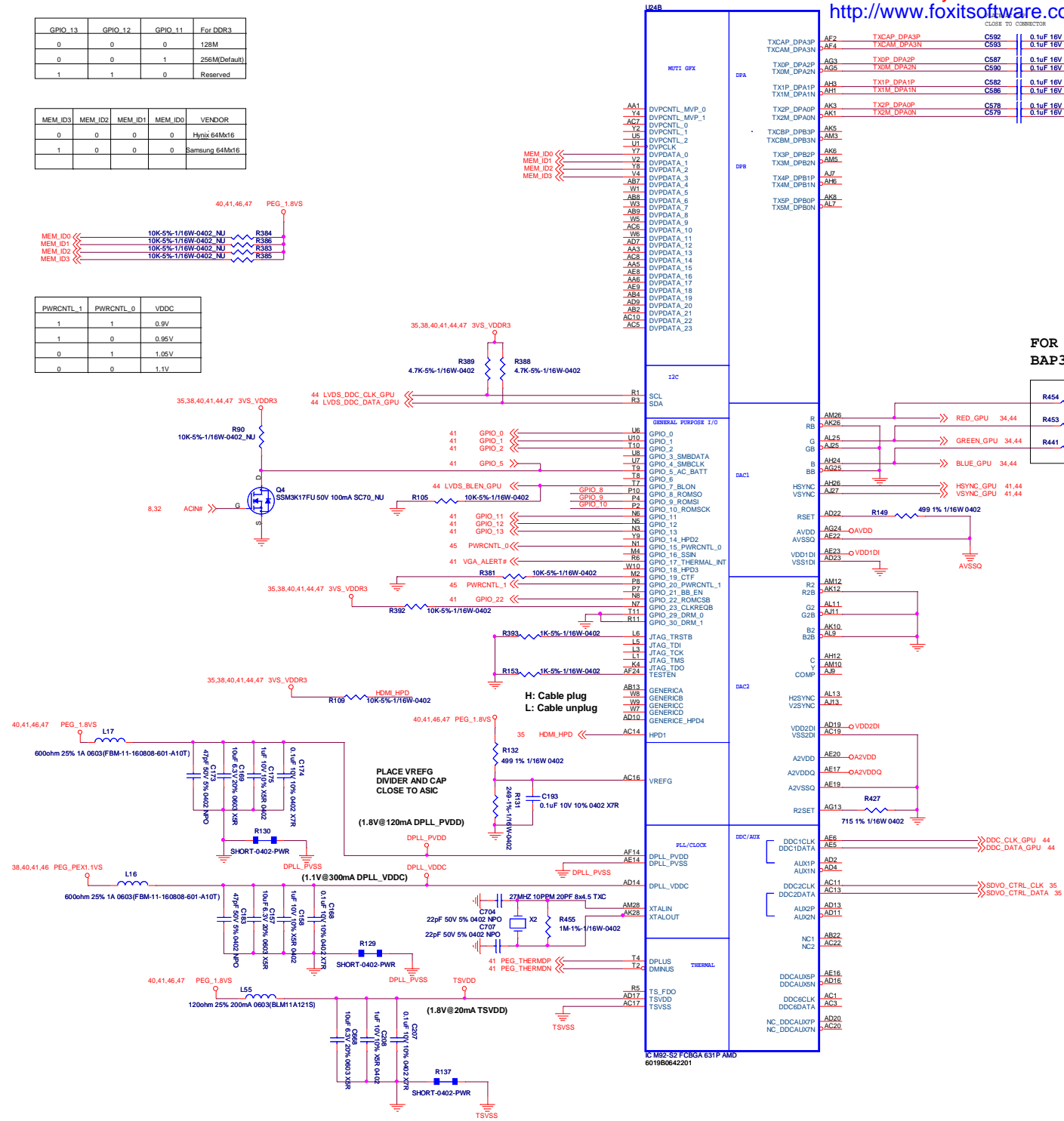
<b>INVENTEC</b>			
TITLE BAP31G SFF BLANK			
SIZE Custom	CODE CS	DOC NUMBER D-CS-1310A224501-ALG	REV A00



GPIO 13	GPIO 12	GPIO 11	For DDR3
0	0	0	128M
0	0	1	256M(Default)
1	1	0	Reserved

MEM_ID3	MEM_ID2	MEM_ID1	MEM_ID0	VENDOR
0	0	0	0	Hynix 64Mx16
1	0	0	0	Samsung 64Mx16

PWRCNTL_1	PWRCNTL_0	VDDC
1	1	0.9V
1	0	0.95V
0	1	1.05V
0	0	1.1V

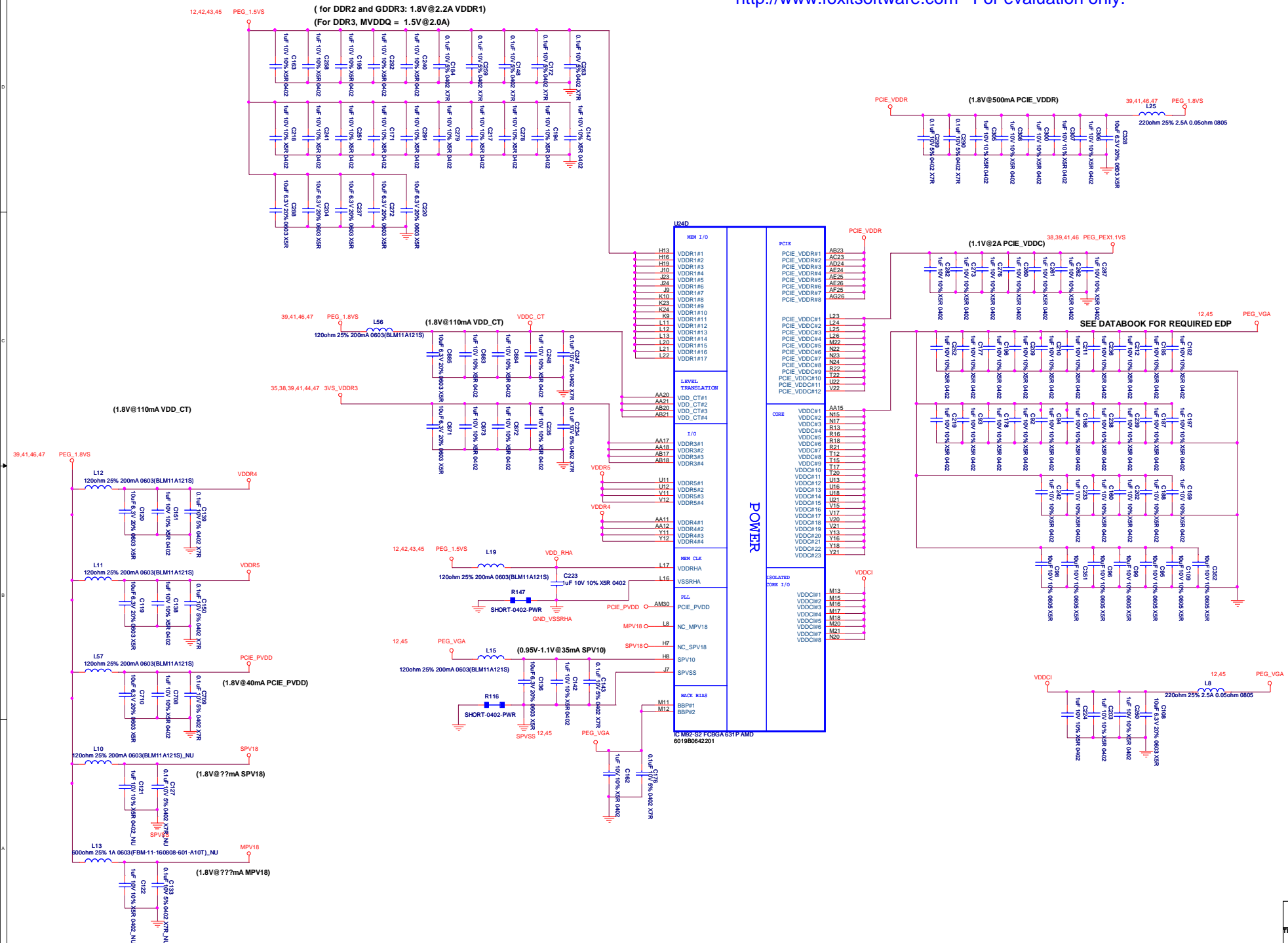


RESERVE SERIAL EEPROM 512K/1M

**INVENTEC**

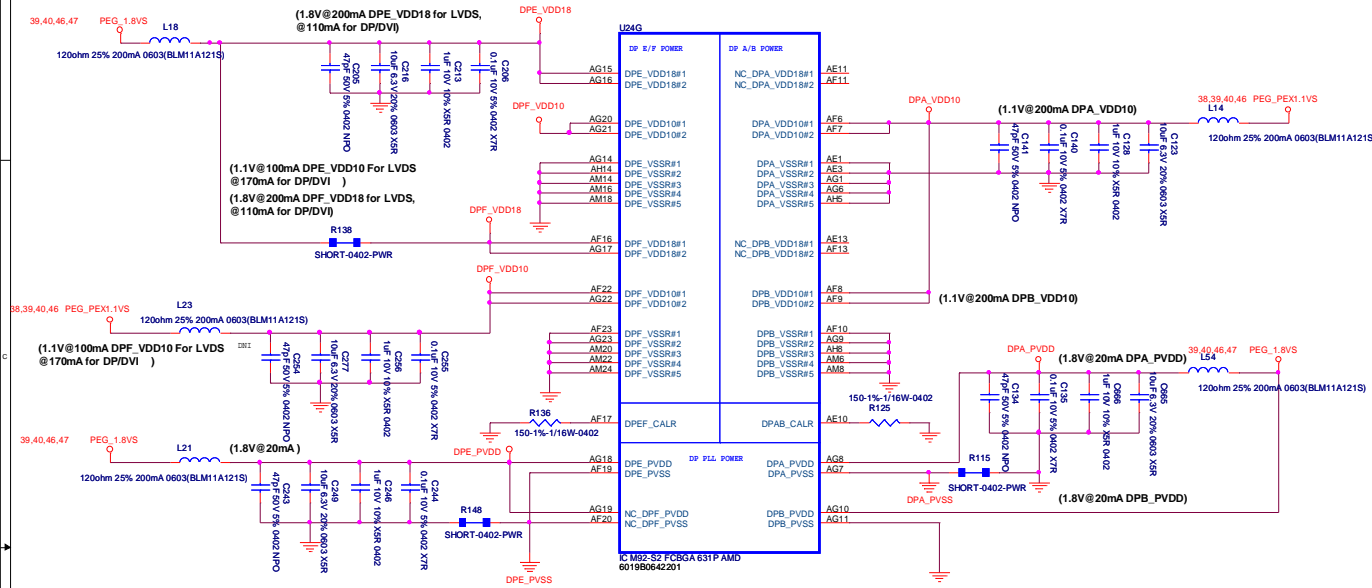
**TITLE**  
**BAP31G SFF**  
**M92 [2/5]**

SIZE	CODE	DOC. NUMBER	REV
Custom	CS	D-CS-1310A2264501-ALG	A03
SHEET		39	of 47

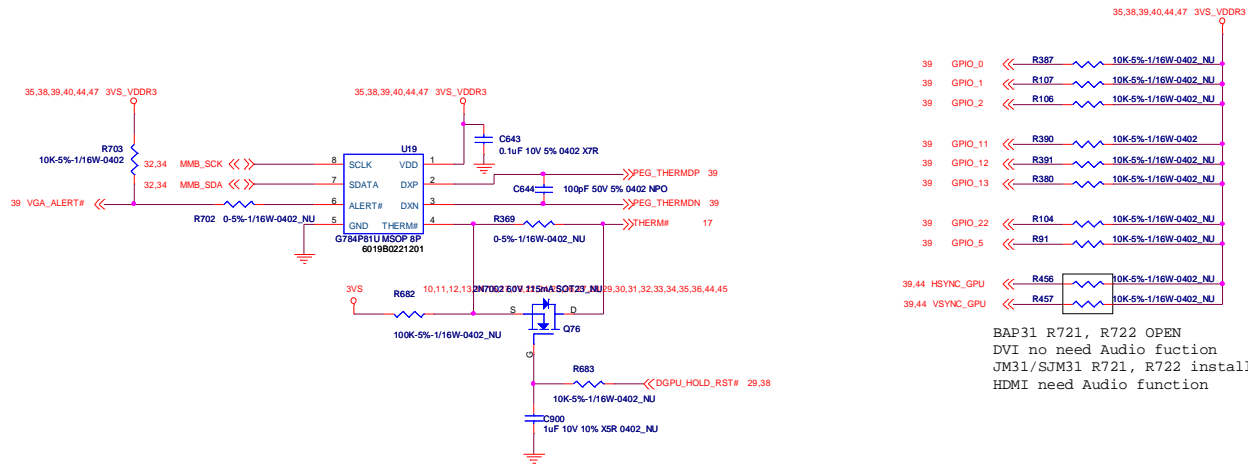




For 92, DPx\_VDD10 = 1.1V  
For Future ASIC, DPx\_VDD10 = 1.0V



## PIN STRAPS



## CONFIGURATION STRAPS

**ALLOW FOR PULLUP PADS FOR THESE STRAPS AND IF THESE GPIOS ARE USED, THEY MUST NOT CONFLICT DURING RESET**

STRAPS	PIN	DESCRIPTION OF DEFAULT SETTINGS	
TX_PWRS_ENB	GPIO0	PCIE FULL TX OUTPUT SWING	X
TX_DEEMPH_EN	GPIO1	PCIE TRANSMITTER DE-EMPHASIS ENABLED	X
BF_GEN2_EN_A	GPIO2	PCE GEN2 ENABLED	X
RSVD	GPIO8		0
BF_VGA_DIS	GPIO9	VGA ENABLED	0
RSVD	GPIO21		0
BIOS_ROM_EN	GPIO_22_ROMCSB	ENABLE EXTERNAL BIOS ROM	X
ROMIDCFG(2:0)	GPIO[13:11]	SERIAL ROM TYPE OR MEMORY APERTURE SIZE SELECT	X X X
VIP_DEVSTRAP_ENA	V2SYNC	IGNORE VIP DEVICE STRAPS	X
RSVD	GENERICC		0
AUD[1]	HSYNC	AUD[1] AUD[0]	0
AUD[0]	VSYNC	0 0 No audio function	0
		0 1 Audio for DisplayPort and HDMI if dongle is detected	X X
		1 0 Audio for DisplayPort only	
		1 1 Audio for both DisplayPort and HDMI	

## AMD RESERVED CONFIGURATION STRAPS

**ALLOW FOR PULLUP PADS FOR THESE STRAPS AND IF THESE GPIOs ARE USED, THEY MUST NOT CONFLICT DURING RESET**

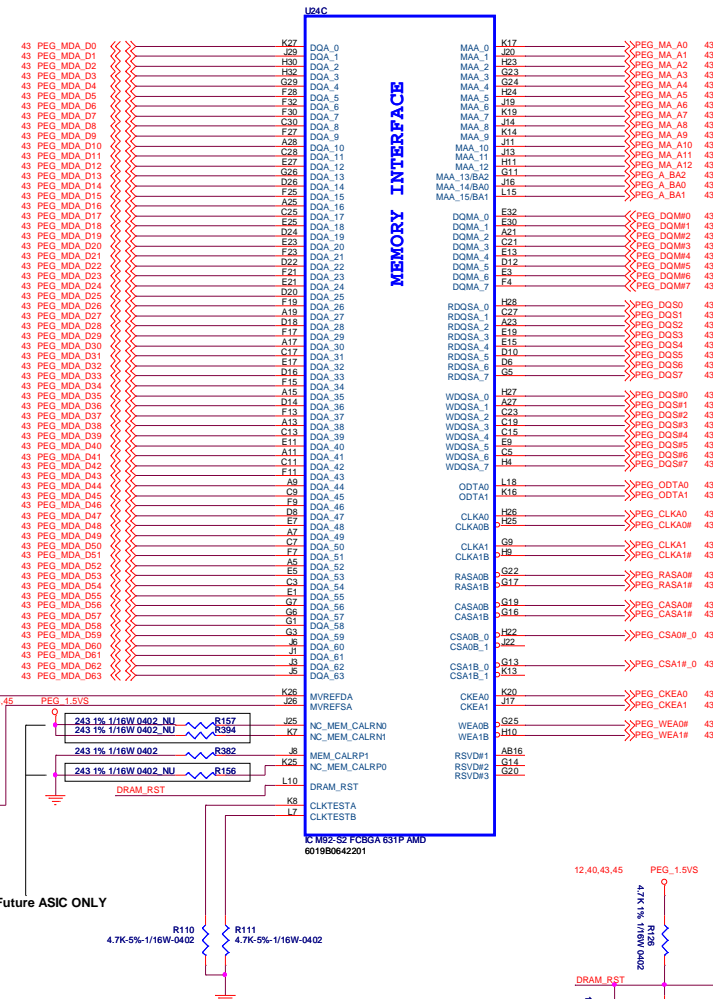
H2SYNC	GENERICC
<p><b>PULLUP PADS ARE NOT REQUIRED FOR THESE STRAPS BUT IF THESE GPIOs ARE USED, THEY MUST NOT CONFLICT DURING RESET</b></p>	
GPIO21_BB_EN	

**INVENTEC**

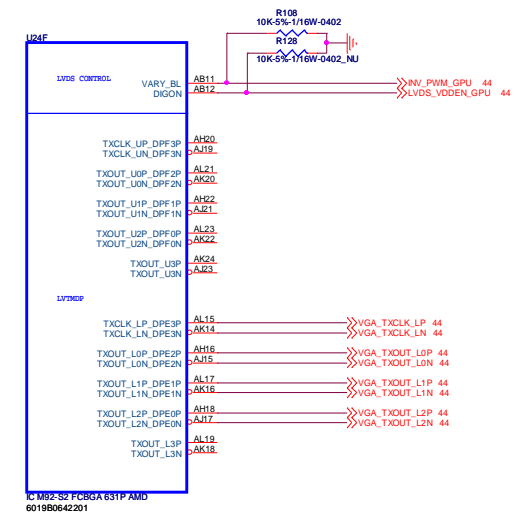
**TITLE**  
**BAP31G SFF**  
**M92 [4/5]**

SIZE Custom	CODE CS	DOC.NUMBER D-CS-1310A2264501-ALG	REV A03
SHEET		41 of	47

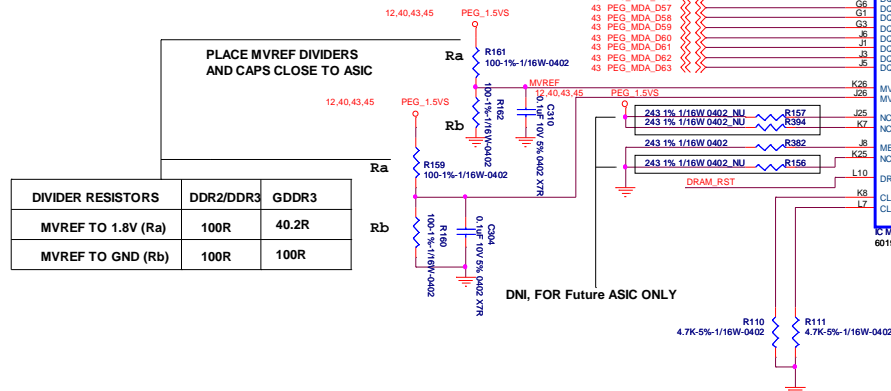
## DDR3 Memory Interface



## LVDS Interface



**MVDDQ = 1.5V FOR  
DDR3 Memory**



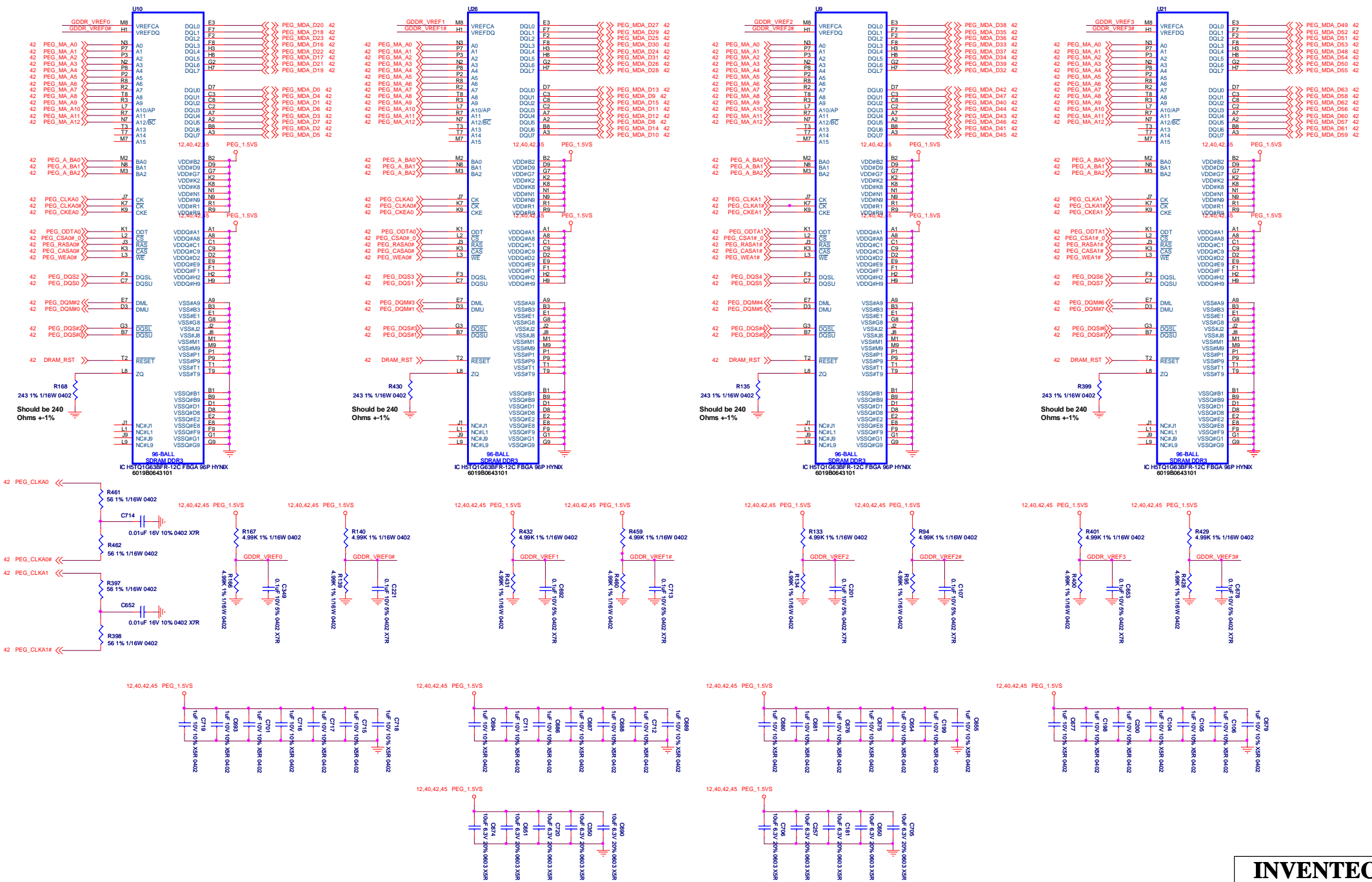
DIVIDER RESISTORS	DDR2/DDR3	GDDR3
MVREF TO 1.8V (Ra)	100R	40.2R
MVREF TO GND (Rb)	100R	100R

DNI, FOR Future ASIC ONLY

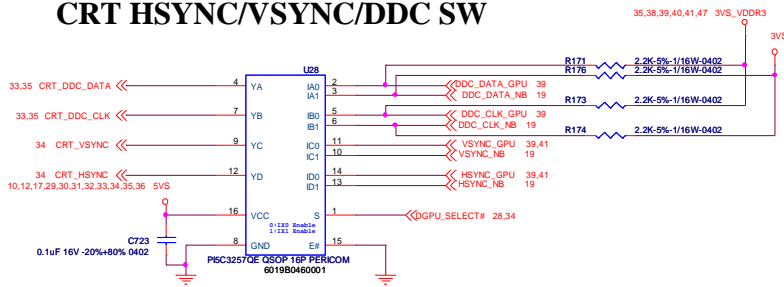
# INVENTEC

**TITLE**  
**BAP31G SFF**

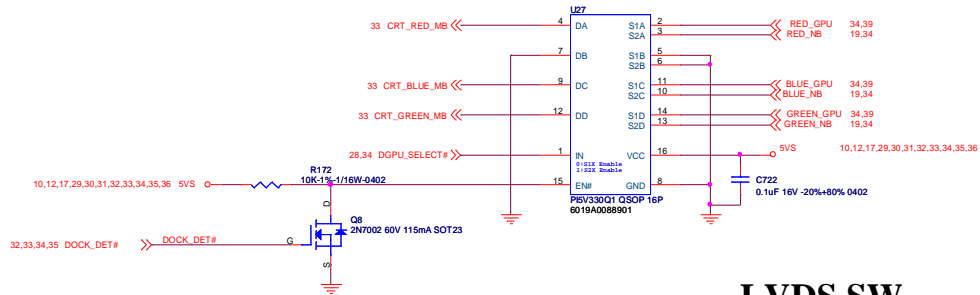
M92 [5/5]			
SIZE Custom	CODE CS	DOC.NUMBER D-CS-1310A2264501-ALG	REV A03
SHEET		42 of	47



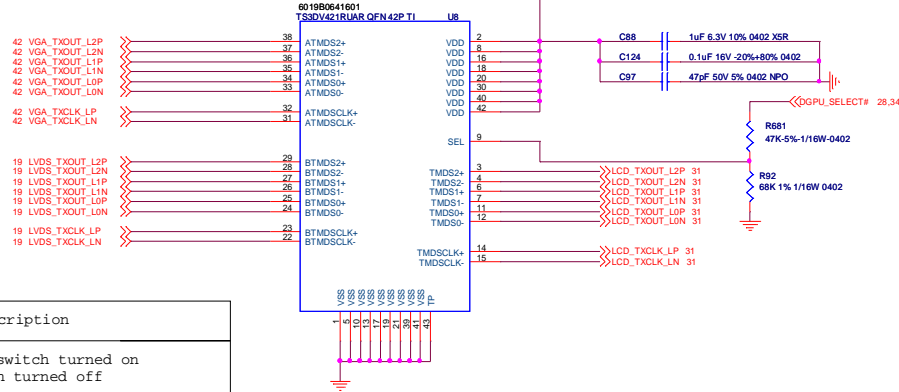
## CRT HSYNC/VSNC/DDC SW



## CRT R/G/B SW



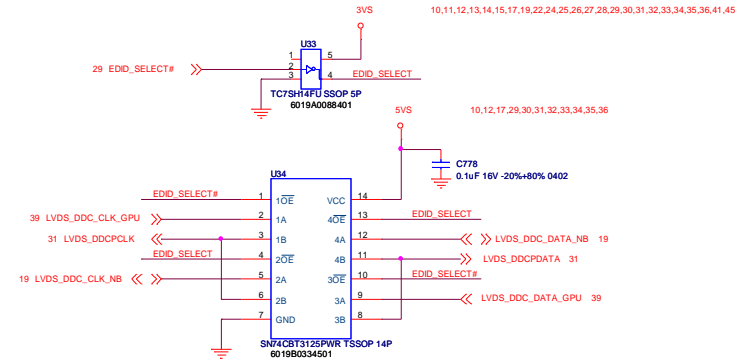
## LVDS SW



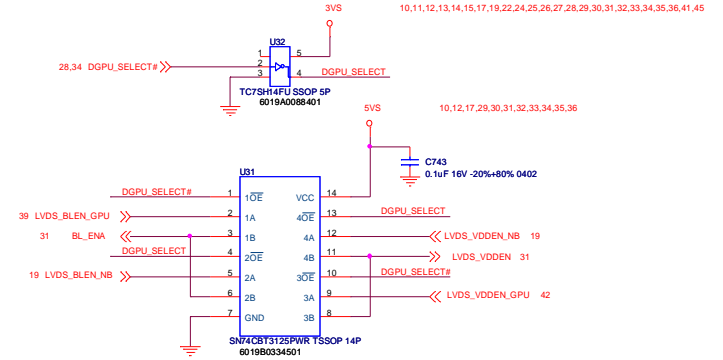
Signal	During Reset	After Reset	Description
DGPU_PWR_EN#	High	High	0 : dGPU power switch turned on 1 : power switch turned off
DGPU_PWROK			0 : dGPU power is not stable 1 : dGPU power is stable
DGPU_HOLD_RST#	Low	Low	0 : Keep dGPU in reset 1 : Reset is released
DGPU_SELECT#	High	High	0 : Display switch enabled for dGPU 1 : Display switch enabled for iGPU
HPD_INT#			0 : DVI insertion 1 : No DVI insertion
PWM_SELECT#		High	0 : PWM switch enabled for dGPU 1 : PWM switch enabled for iGPU
EDID_SELECT#		High	0 : EDID/DDC switch enabled for dGPU 1 : EDID/DDC switch enabled for iGPU

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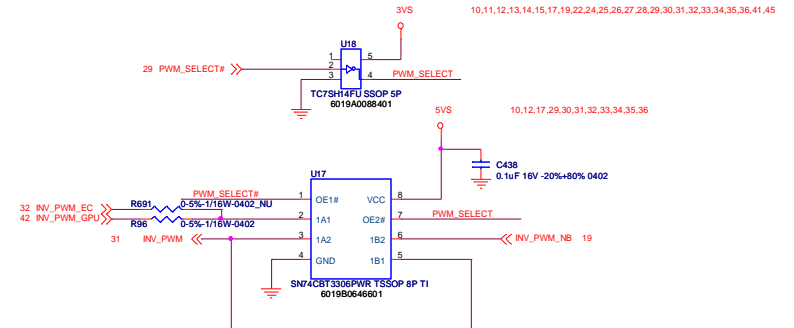
## LCD DDC SW



## LVDS BKL and Vcc Enable SW

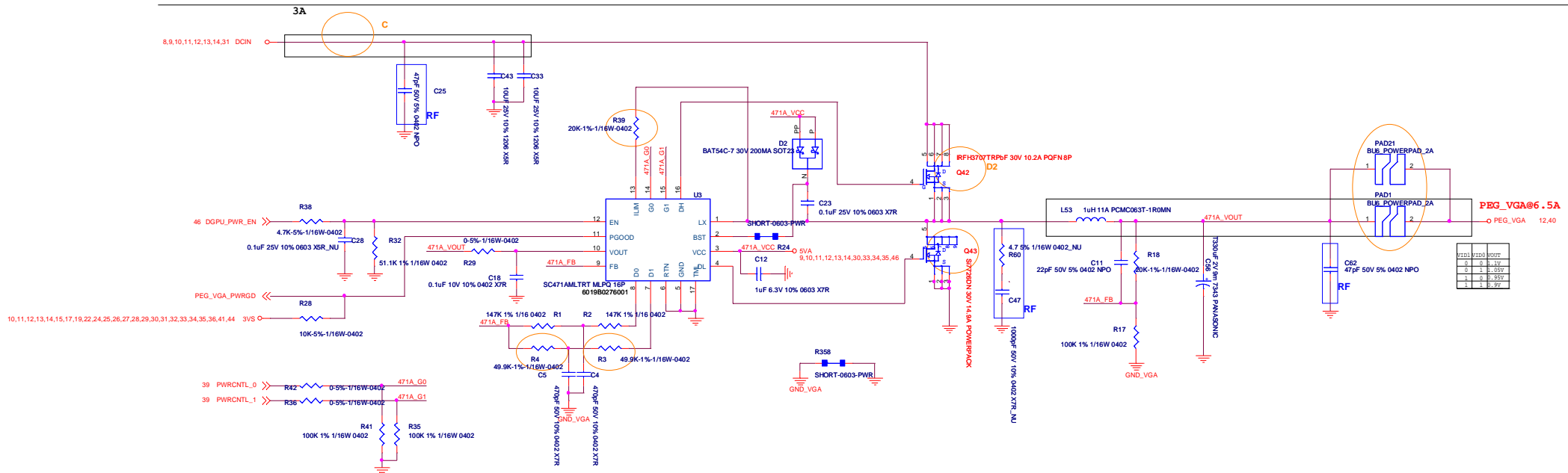
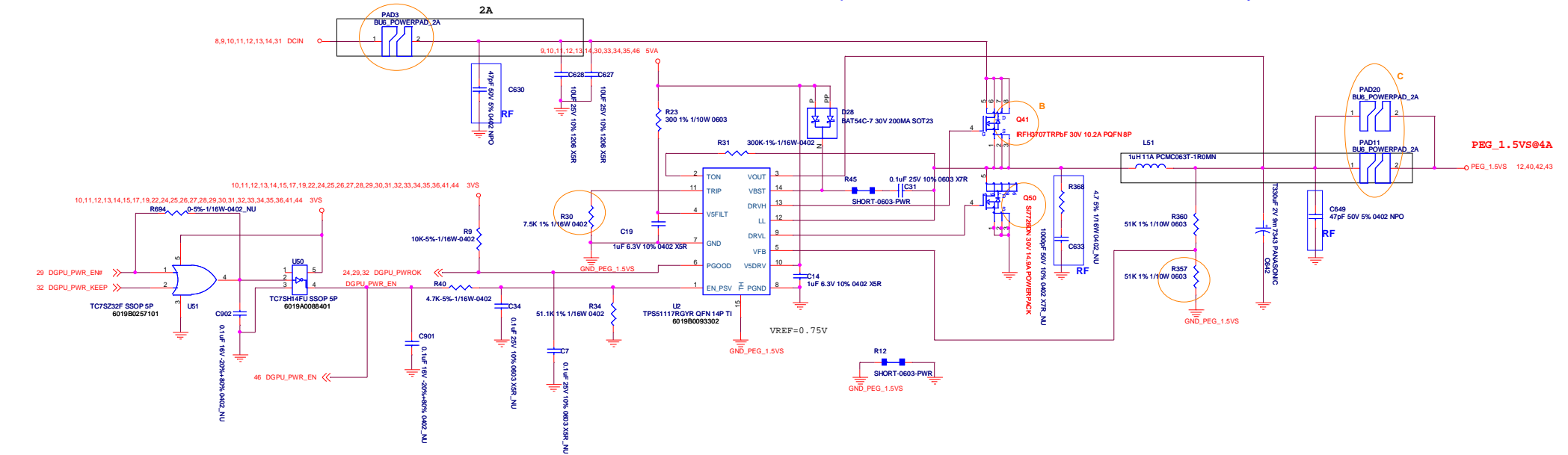


## LCD PWM SW



**INVENTEC**

BAP31G SFF			
Hybrid Switch			
SIZE	CODE	DOCNUMBER	REV
Custom	CS	D-CS-1310A2284501-ALG	A03
SHEET	44	of	47



PWRCNTL_1	PWRCNTL_0	VDDC
1	1	0.9V
1	0	0.95V
0	1	1.05V
0	0	1.1V

